life.augmented

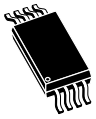
M24512E-F

Datasheet

512-Kbit serial I²C bus EEPROM with configurable device address and software write protection registers

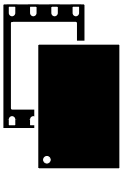
SO8N

150 mil width



TSSOP8

169 mils width



UFDFPN8

DFN8 - 2x3 mm

Product status link
M24512E-F

Features

- Compatible with following I²C bus modes:
  - 1 MHz (Fast-mode Plus)
  - 400 kHz (Fast-mode)
  - 100 kHz (Standard-mode)
- Memory array:
  - 512 Kbit (64 Kbyte) of EEPROM
  - Page size: 128 byte
  - Additional identification page
- Device type identifier register (in read-only)
- Configurable device address register
- Software write protection register
- Hardware write protection of the whole memory array
- Single supply voltage:
  - From 1.6 V to 5.5 V
- Write cycle time:
  - Byte write within 4 ms
  - Page write within 4 ms
- Operating temperature range:
  - -40 °C up to +85 °C
- Random and sequential read modes
- Enhanced ESD/Latch-Up protection
- More than 4 million write cycles
- More than 200-year data retention
- Package:
  - SO8N ECOPACK2
  - TSSOP8 ECOPACK2
  - UFDFPN8 ECOPACK2

1 Description

The M24512E-F is a 512-Kbit I²C-compatible EEPROM (electrically erasable programmable memory) organized as 64 K × 8 bits.

The M24512E-F can operate with a supply voltage from 1.6 V to 5.5 V with a clock frequency of 1 MHz (or less), over an ambient temperature range of -40 °C / +85 °C.

The M24512E-F offers three 8-bit registers. The device type identifier (DTI) register permanently locked in read-only mode. The configurable device address (CDA) register authorizing the user, through software, to configure up to eight possibilities of chip enable address. The software write protection (SWP) register authorizing the user, through software, to write protect partial or full memory array.

Moreover, the M24512E-F offers an additional page, named the identification page (128 byte). The identification page can be used to store sensitive application parameters which can be (later) permanently locked in read-only mode.

The M24512E-F is available in the standard 8-pin TSSOP,SO8N and UFDFPN8 with the $\overline{WC}$ pin.

Figure 1. Logic diagram

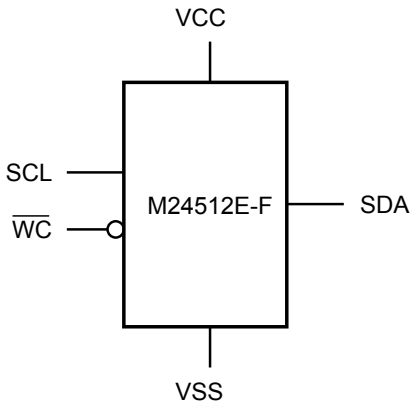
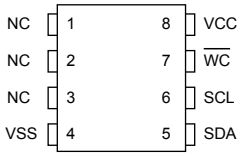


Table 1. Signal names

Signal name	Function	Direction
SDA	Serial data	I/O
SCL	Serial clock	Input
$\overline{WC}$	Write control	Input
V_{CC}	Supply voltage	-
V_{SS}	Ground	-

Figure 2. 8-pin package connections, top view



DT54532V1

1. NC: Not connected

See Section 10 Package information for package dimensions, and how to identify pin 1.

2 Signal description

2.1 Serial clock (SCL)

The signal applied on the SCL input is used to strobe the data available on SDA(in) and to output the data on SDA(out).

2.2 Serial data (SDA)

SDA is an input/output used to transfer data in or data out of the device. SDA(out) is an open drain output that may be wired-AND with other open drain or open collector signals on the bus. A pull-up resistor must be connected from serial data (SDA) to V_{CC} (Figure 24 and Figure 25 indicate how to calculate the value of the pull-up resistor).

2.3 Write control ($\overline{WC}$)

This input signal is useful for protecting the contents of the memory, registers and identification page from inadvertent write operations. All write operations are disabled when write control ($\overline{WC}$) is driven high. All write operations are enabled when write control ($\overline{WC}$) is either driven low or left floating.

When write control ($\overline{WC}$) is driven high, device select and address bytes are acknowledged, data bytes are not acknowledged.

2.4 V_{SS} (ground)

V_{SS} is the reference for the V_{CC} supply voltage.

2.5 Supply voltage (V_{CC})

2.5.1 Operating supply voltage (V_{CC})

Prior to selecting the memory and issuing instructions to it, a valid and stable V_{CC} voltage within the specified [V_{CC}(min), V_{CC}(max)] range must be applied (see operating conditions in Section 9 DC and AC parameters). In order to secure a stable DC supply voltage, it is recommended to decouple the V_{CC} line with a suitable capacitor (usually of the order of 10 nF to 100 nF) close to the VCC/VSS package pins.

This voltage must remain stable and valid until the end of the transmission of the instruction and, for a write instruction, until the completion of the internal write cycle (t_W).

2.5.2 Power-up conditions

The V_{CC} voltage has to rise continuously from 0 V up to the minimum V_{CC} operating voltage (see operating conditions in Section 9 DC and AC parameters).

Once the V_{CC} is greater than, or equal to, the minimum V_{CC} level, the master must wait for at least T_{WU} before sending the first command to the device. See Table 18 and Table 19 for the value of the wake-up time parameter.

2.5.3 Device reset

In order to prevent inadvertent write operations during power-up, a power-on-reset (POR) circuit is included.

At power-up, the device does not respond to any instruction until V_{CC} has reached the internal reset threshold voltage. This threshold is lower than the minimum V_{CC} operating voltage (see operating conditions in Section 9 DC and AC parameters). When V_{CC} passes over the POR threshold, the device is reset and enters the standby power mode; however, the device must not be accessed until V_{CC} reaches a valid and stable DC voltage within the specified [V_{CC}(min), V_{CC}(max)] range (see operating conditions in Section 9 DC and AC parameters).

In a similar way, during power-down (continuous decrease in V_{CC}), the device must not be accessed when V_{CC} drops below V_{CC}(min). When V_{CC} drops below the power-on-reset threshold voltage, the device stops responding to any instruction sent to it.

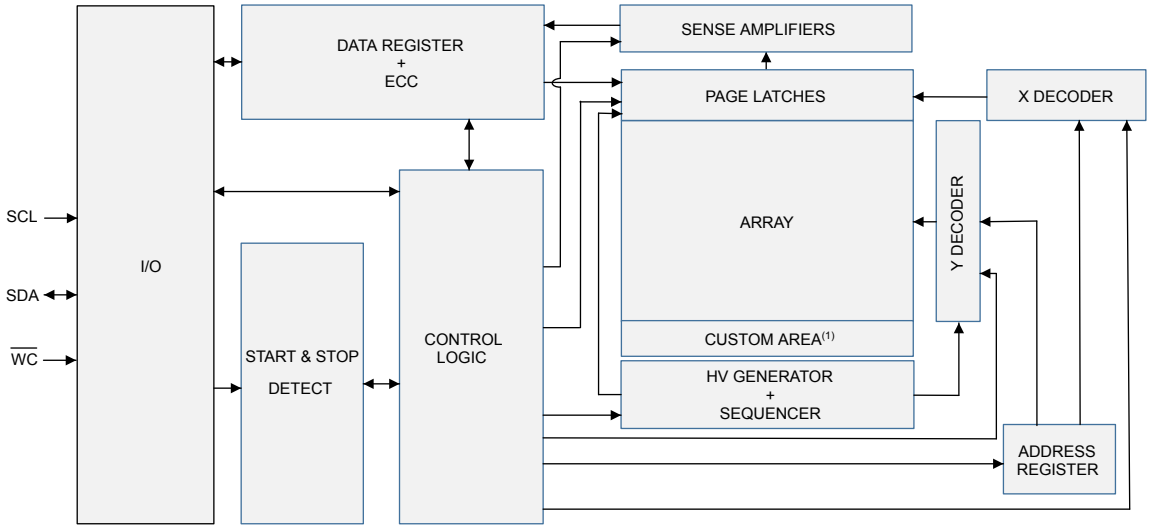
2.5.4 Power-down conditions

During power-down (continuous decrease in V_{CC}), the device must be in the standby power mode (mode reached after decoding a stop condition, assuming that there is no internal write cycle in progress).

3 Memory organization

The memory is organized as shown below.

Figure 3. Block diagram



1. DTI, CDA, SWP registers and identification page.

4 Device features

The device type identifier 1011 must be used to address the DTI, SWP, CDA registers and the identification page.

4.1 Device type identifier register (DTI)

The device type identifier register (DTI), is an 8-bit register permanently locked in read-only mode. This register is factory programmed with device type identifier bits (DTI3, DTI2, DTI1 and DTI0) set to ‘1011’ and with device type identifier lock bit (DTIL) set to '1' to freeze definitively the register. DTI3, DTI2, DTI1 and DTI0 are defining the device type identifier address in the device select code. At power up, the device loads the last configuration of DTI3, DTI2, DTI1, DTI0 and DTIL values.

This register is read by issuing the read device type identifier instruction. This instruction uses the same protocol and format as the random address read (from memory array) except for the following differences (refer to Table 8, Table 9 and Table 10).

- Device type identifier = 1011b
- MSB address bits A15/A14/A13 must be equal to '111' (A15=1, A14=1 and A13=1)
- MSB address bits A12/A8 are don't care
- LSB address bits A7/A0 are don't care

The description of the configurable device address register is given in Table 2.

Table 2. Device type identifier register

bit 7	bit 6	bit 5	bit 4	bit 3	bit 2	bit 1	bit 0
DTI3=1	DTI2=0	DTI1=1	DTI0=1	X(1)	X	X	DTIL=1

1. *X = Don’t care bit. Read as '0'.*

Note: Factory delivery of the register is 10110001b

Table 3. Device type identifier register description

Bit	Function
Bits b7 to b4	**DTI3, DTI2, DTI1, DTI0** : Device type identifier bits. b7, b6, b5, b4 are used to configure the device type identifier of the device select code. • (b7, b6, b5, b4)=(1, 0, 1, 1) the device type identifier is '1011' (factory default value) Note: Bits b7 to b4 are frozen at factory delivery.
Bits b3 to b1	Reserved bits. Read as ‘0’. (b3, b2, b1)=(0, 0, 0)
Bit b0	**DTIL**: Device type identifier lock bit. b0 indicates the DTI register status is in read-only mode. • (b0)= (1) the device type identifier lock bit is equal to 1 (factory default value) Note: Bit b0 is frozen at factory delivery.

4.2 Configurable device address register (CDA)

The configurable device address register (CDA) is an 8-bit register allowing the user to define a configurable device address (C2, C1 and C0) and a specific bit, named device address lock (DAL), to freeze definitively the configurable device address register. This register can be read and written by issuing the read or write configurable device address instruction. These instructions use the same protocol and format as the random address read or page write (from/into memory array) except for the following differences (refer to Table 8, Table 9 and Table 10):

- Device type identifier = 1011b
- MSB address bits A15/A14/A13 must be equal to '110' (A15=1, A14=1 and A13=0)
- MSB address bits A12/A8 are don't care
- LSB address bits A7/A0 are don't care

C2, C1, C0 and DAL are defining the chip enable address in the device select code and the device address lock. These bits can be written and re-configured with a write command.

At power up or after reprogramming, the device load the last configuration of C2, C1, C0 and DAL values.

To prevent unwanted change of configurable device address bits, the M24512E-F proposes to protect the CDA register, freezing permanently it in read-only mode. The update of the CDA register is disabled (read-only) when the DAL bit is set to '1' (DAL=1b).

In the same way, the update of the CDA register is enabled when the DAL bit is set to '0' (DAL= 0b).

Sending more than one byte during a write configurable device address command aborts the write cycle (CDA register content doesn't change).

Note:

- *Updating the DAL bit from '0' to '1' is an irreversible action: the C2, C1, C0 and DAL bits cannot be updated any more.*
- *If the write control input ($\overline{WC}$) is driven high or if the DAL bit is set to '1', the write configurable device address command is not executed and the accompanying data byte is not acknowledged, as shown in Figure 6 and write cycle does not start.*

The description of the configurable device address register is given in Table 4:

Table 4. Configurable device address register

bit 7	bit 6	bit 5	bit 4	bit 3	bit 2	bit 1	bit 0
X (1)	X	X	X	C2	C1	C0	DAL

1. *X = Don't care bits. Read as 0.*

Note: Factory delivery of the CDA register is 00000000b.

Table 5. **Configurable device address register description**

Bit	Function
Bits b7 to b4	Reserved bits - Read as '0'. (b7, b6, b5, b4)=(0,0,0,0)
Bits b3 to b1	**C2, C1, C0**: Configurable device address bits. b3, b2, b1 are used to configure up to eight possibilities of chip enable address: • (b3, b2, b1) = (0, 0, 0): the chip enable address is 000 (factory delivery value) • (b3, b2, b1) = (0, 0, 1): the chip enable address is 001 • (b3, b2, b1) = (0, 1, 0): the chip enable address is 010 • (b3, b2, b1) = (0, 1, 1): the chip enable address is 011 • (b3, b2, b1) = (1, 0, 0): the chip enable address is 100 • (b3, b2, b1) = (1, 0, 1): the chip enable address is 101 • (b3, b2, b1) = (1, 1 0): the chip enable address is 110 • (b3, b2, b1) = (1, 1, 1): the chip enable address is 111
Bit b0	**DAL**: Device address lock bit. b0 locks the CDA register in read-only mode: • b0 = 0: bits b3, b2, b1, b0 can be modified • b0 = 1: bits b3, b2, b1, b0 cannot be modified and therefore the CDA register is frozen Note: Bits b3 to b0 can be updated (if b0 = 0) in the same write instruction. Setting b0 from 0 to 1 is an irreversible action.

4.3 Software write protection register (SWP)

The software write protection (SWP) register is a non-volatile 8-bit register allowing the user to protect a specific area of the memory against the write instruction. The SWP offers four non volatile bits to configure by the user:

- Two bits for setting the size of the write-protected memory and identified as block protection (BP0, BP1) bits
- One bit to enable / disable the write protection of the desired area and identified as write protect activation (WPA) bit
- One bit to definitively freeze in read-only mode the SWP register and identified as write protection lock (WPL) bit

This register can be read and written by issuing the read or write software write protection register instructions. These instructions use the same protocol and format as the random address read or page write (from/into memory array) except for the following differences (refer to Table 8, Table 9 and Table 10):

- Device type identifier = 1011b
- MSB address bits A15/A14/A13 must be equal to '101' (A15=1; A14=0; A13=1)
- MSB address bits A12/A8 are don't care
- LSB address bits A7/A0 are don't care

BP1 and BP0 are the block protection bits. WPL is the write protect lock bit and WPA is the write protect activation bit. These bits can be written and re-configured with a write command. At power up, the device loads the last configuration of the SWP register value.

The user can update the SWP register as often as the WPL bit stays at '0'.

Writing more than one byte discard the write cycle (software write protection register content is not changed).

To prevent unwanted change of software write protection register bits, the M24512E-F proposes to protect the SWP register, freezing it permanently in read-only mode. The update of the SWP register is disabled (read only) when the WPL bit is set to '1' (WPL = 1b). In the same way, the update of the SWP register is enabled when the WPL bit is set to '0' (WPL = 0b).

When WPL is set to '1' and in case of write software write protection register, the device select and address bytes are acknowledged, data byte is not acknowledged and write cycle does not start.

Note:

- *Updating the WPL bit from 0 to 1 is an irreversible action: the WPA, BP1, BP0 and WPL bits cannot be updated any more*
- *If the write control input ($\overline{WC}$) is driven high or if the WPL bit is set to 1, the write configurable device address command is not executed and the accompanying data byte is not acknowledged, as shown in Figure 6*

The description of the software write protection register is given in Table 6:

Table 6. Software write protection register values

bit 7	bit 6	bit 5	bit 4	bit 3	bit 2	bit 1	bit 0
X (1)	X	X	X	WPA	BP1	BP0	WPL

1. *X = Don't care bits. Read as 0.*

Note: Factory delivery of the SWP register is 00000000b.

Table 7. Software write protection register description

Bit	Function
Bits b7 to b4	• Reserved bits. Read as '0'. (b7, b6, b5, b4)=(0,0,0,0)
Bits b3	**WPA**: Write protect activation bit. b3 enables or disables the write protection: • b3 = 0: no write protection. The whole memory can be written. • b3 = 1: write protection active. The memory block is protected according to BP bits setting.
Bits b2 to b1	**BP1, BP0**: block protection bits b2 and b1 define the size of the memory block to be protected against write instruction: • (b2,b1) = (0,0): the upper quarter of memory is write-protected • (b2,b1) = (0,1): the upper half of memory is write protected • (b2,b1) = (1,0): the upper ¾ of memory is write protected • (b2,b1) = (1,1): the whole memory is write protected
Bit b0	**WPL**: write protection lock bit b0 locks the write protection register value. • b0 = 0: bits [b3: b0] can be modified • b0 = 1: bits [b3: b0] cannot be modified and therefore the write protection register is frozen. Note: bits b3 to b0 can be updated (if b0 = 0) in the same write instruction. Setting b0 from 0 to 1 is an irreversible action.

4.4 Identification page

The identification page (128 bytes) is an additional page, which can be read or written and (later) permanently locked in read-only mode. It is read or written by issuing the read or write identification page instruction. These instructions use the same protocol and format as the random address read or page write (from/into memory array) except for the following differences (refer to Table 8, Table 9 and Table 10):

- Device type identifier = 1011b
- MSB address bits A15/A14/A13 must be equal to '000' (A15 = 0, A14 = 0 and A13 = 0)
- MSB address bits A12/A8 are don't care
- LSB address bit A7 is don't care, bits A6/A0 define the byte address inside the identification page

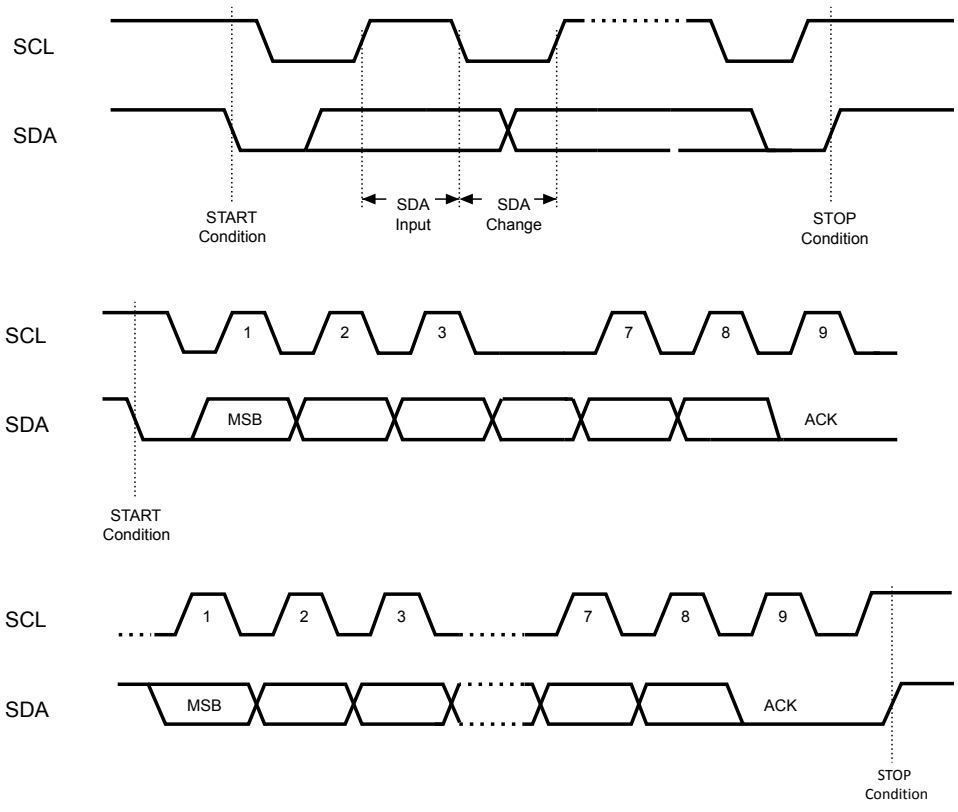
If the identification page is locked, the data bytes transferred during the write identification page instruction are not acknowledged (NoACK).

The identification page is filled with all bytes written to FFh.

5 Device operation

The device supports the I²C protocol. This is summarized in Figure 4. Any device that sends data on to the bus is defined to be a transmitter, and any device that reads the data is defined to be a receiver. The device that controls the data transfer is known as the bus master, and the other as the slave device. A data transfer can only be initiated by the bus master, which also provides the serial clock for synchronization. The device is always a slave in all communications.

Figure 4. I²C bus protocol



5.1 Start condition

Start is identified by a falling edge of serial data (SDA) while serial clock (SCL) is stable in the high state. A start condition must precede any data transfer instruction. The device continuously monitors (except during a write cycle) serial data (SDA) and serial clock (SCL) for a start condition.

5.2 Stop condition

Stop is identified by a rising edge of serial data (SDA) while serial clock (SCL) is stable in the high state. A stop condition terminates communication between the device and the bus master. A read instruction that is followed by NoAck can be followed by a stop condition to force the device into the standby mode.

A stop condition at the end of a write instruction triggers the internal write cycle.

5.3 Data input

During data input, the device samples serial data (SDA) on the rising edge of serial clock (SCL). For correct device operation, serial data (SDA) must be stable during the rising edge of serial clock (SCL), and the serial data (SDA) signal must change only when serial clock (SCL) is driven low.

5.4 Acknowledge bit (ACK)

The acknowledge bit is used to indicate a successful byte transfer. The bus transmitter, whether it be bus master or slave device, releases serial data (SDA) after sending eight bits of data. During the 9^{th} clock pulse period, the receiver pulls serial data (SDA) low to acknowledge the receipt of the eight data bits.

5.5 Device addressing

To start communication between the bus master and the slave device, the bus master must initiate a Start condition. Following this, the bus master sends the device select code and byte address as specified in Table 8, Table 9 and Table 10.

When the device select code is received, the device responds only if the bits b3, b2 and b1 values match the values of the C2, C1 and C0 bits programmed in the configurable device address register.

If a match occurs, the corresponding device gives an acknowledgement on serial data (SDA) during the 9th bit time.

If the device does not acknowledge the device select code, the device de-selects itself from the bus, and goes into Standby mode (therefore it does not acknowledge the device select code).

The 8th bit is the read/write bit ($R\overline{W}$). This bit is set to '1' for read and '0' for write operations

Table 8. Device select code

Features	Device type identifier				Chip enable address(1)			$R\overline{W}$
	Bit 7 (MSB)(2)	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0 (LSB)
Memory	1	0	1	0	C2	C1	C0	$R\overline{W}$
Device type identifier	1	0	1	1	C2	C1	C0	$R\overline{W}$
Configurable device address	1	0	1	1	C2	C1	C0	$R\overline{W}$
Software write protection	1	0	1	1	C2	C1	C0	$R\overline{W}$
Identification page	1	0	1	1	C2	C1	C0	$R\overline{W}$
Identification page lock	1	0	1	1	C2	C1	C0	$R\overline{W}$

1. *C0, C1 and C2 are compared with the value read on bits b1,b2 and b3 of the CDA register.*
2. *The most significant bit, b7, is sent first.*

Table 9. First byte address

Features	Bit 7 (MSB)(1)	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0 (LSB)
Memory	A15	A14	A13	A12	A11	A10	A9	A8
Device type identifier	1	1	1	X(2)	X	X	X	X
Configurable device address	1	1	0	X	X	X	X	X
Software write protection	1	0	1	X	X	X	X	X
Identification page	0	0	0	X	X	X	X	X
Identification page lock	0	1	1	X	X	X	X	X

1. *The most significant bit, b7, is sent first.*
2. *X = Don't care bit*

Table 10. Second byte address

Features	Bit 7 (MSB)(1)	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0 (LSB)
Memory	A7	A6	A5	A4	A3	A2	A1	A0
Device type identifier	X(2)	X	X	X	X	X	X	X
Configurable device address	X	X	X	X	X	X	X	X
Software write protection	X	X	X	X	X	X	X	X
Identification page	X	A6	A5	A4	A3	A2	A1	A0
Identification page lock	X	X	X	X	X	X	X	X

1. *The most significant bit, b7, is sent first.*
2. *X = Don't care bit*

6 Instructions

6.1 Write operations on memory array

Following a start condition the bus master sends a device select code with the R/W bit ($R\overline{W}$) reset to 0. The device acknowledges this, as shown in Figure 5, and waits for two address bytes. The device responds to each address byte with an acknowledge bit, and then waits for the data byte. See in Section 5.5 Device addressing (Table 8, Table 9 and Table 10) how to address the memory array.

When the bus master generates a stop condition immediately after a data byte Ack bit (in the "10^{th} bit" time slot), either at the end of a byte write or a page write, the internal write cycle t_W is triggered. A stop condition at any other time slot does not trigger the internal write cycle.

After the stop condition and the successful completion of an internal write cycle (t_W), the device internal address counter is automatically incremented to point to the next byte after the last modified byte.

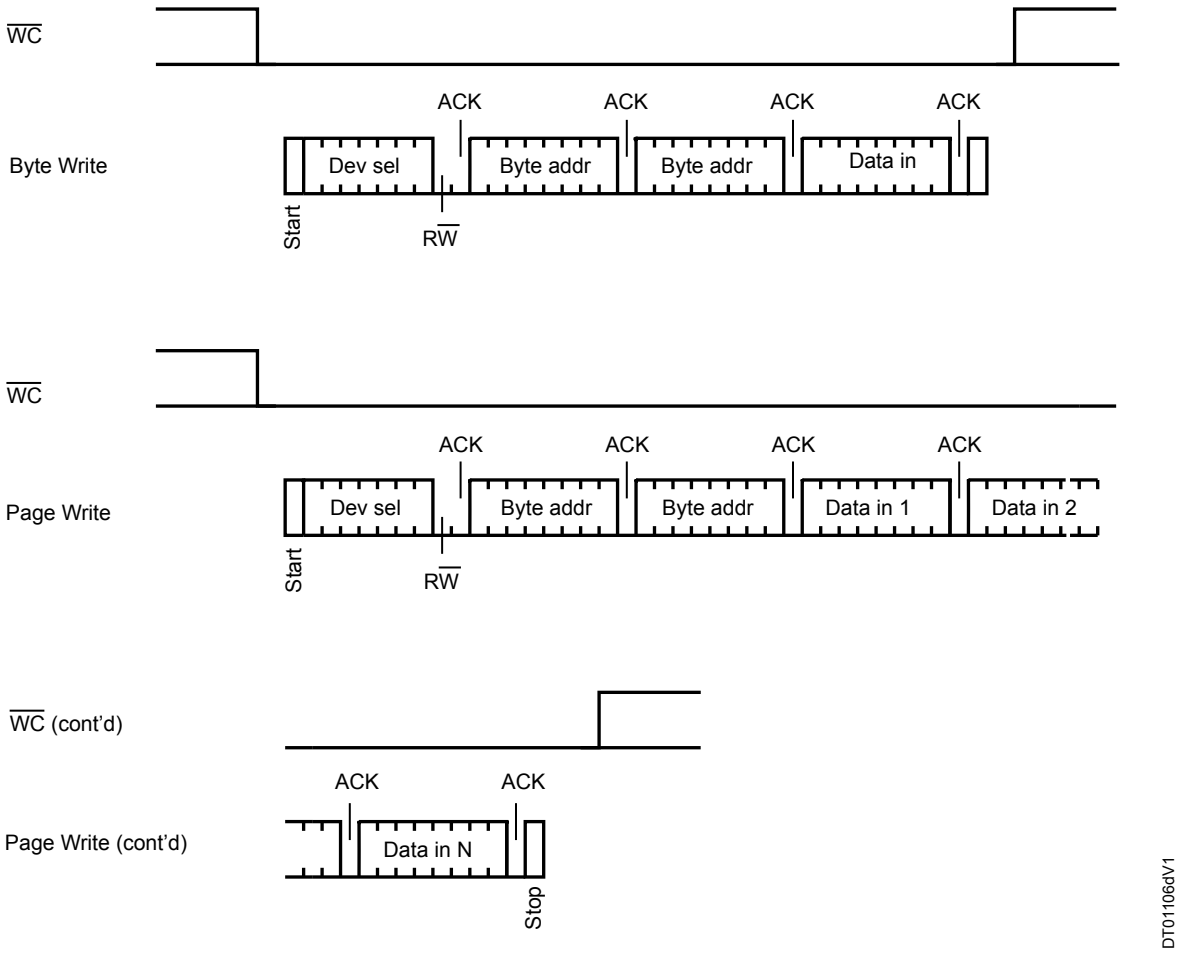
During the internal write cycle, serial data (SDA) is disabled internally, and the device does not respond to any requests.

If the addressed area is write protected by software through the SWP setting or hard protected through $\overline{WC}$ pin driven high, the write instruction is not executed and the accompanying data bytes are not acknowledged, as shown in Figure 6.

6.1.1 Byte write

After the device select code and the address bytes, the bus master sends one data byte. If the addressed location is write-protected, through the SWP setting or through $\overline{WC}$ pin being driven high, the device replies with NoAck, and the location is not modified. If, instead, the addressed location is not write-protected, the device replies with Ack. The bus master terminates the transfer by generating a stop condition, as shown in Figure 5.

Figure 5. Write mode sequences without write protection (data write enabled)



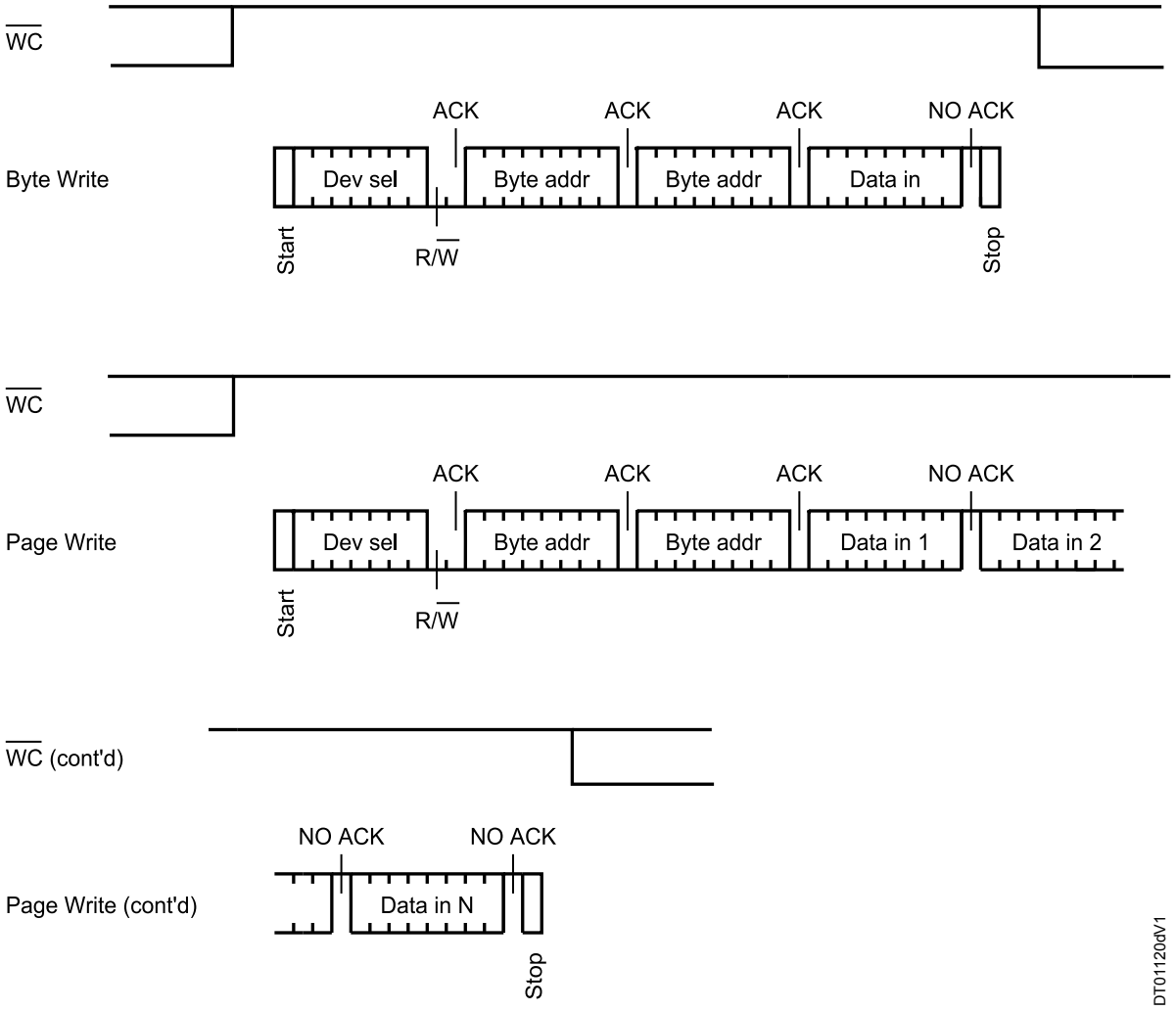
6.1.2 Page write

The page write mode allows up to 128 byte to be written in a single write cycle, provided that they are all located in the same page in the memory: that is, the most significant memory address bits, A15/A7, are the same. If more bytes are sent than fit up to the end of the page, a “roll-over” occurs, i.e. the bytes exceeding the page end are written on the same page, from location 0.

The bus master sends from 1 to 128 byte of data, each of which is acknowledged by the device if the addressed bytes are not write-protected, through the SWP setting or through $\overline{WC}$ pin (driven low). In the opposite case, when the addressed bytes are write-protected by SWP settings or $\overline{WC}$ pin (driven high), the contents of the addressed memory location are not modified, and each data byte is followed by a NoAck, as shown in Figure 6. After each transferred byte, the internal page address counter is incremented.

The transfer is terminated by the bus master generating a stop condition.

Figure 6. Write mode sequences with write protection (data write inhibited)



6.2 Write operations on features

6.2.1 Write operation on DTI register

Write operations on device type identifier (DTI) register are not allowed.

The register is delivered locked in read-only.

6.2.2 Write operation on CDA register

Write operations on configurable device address register are performed according to the state of the device address lock bit (DAL) or the status of $\overline{WC}$ line.

If the configurable device address register is write protected by software with DAL=1 or hard protected with $\overline{WC}$ line driven high, the write operation on this register is not executed and the accompanying data byte is not acknowledged as shown in Figure 8.

Following a start condition the bus master sends a device select code with the R/W bit ($\overline{RW}$) set to 0. The device acknowledges this, as shown in Figure 7, and waits for the address bytes where the register is located. The device responds to each address byte with an acknowledge bit, and then waits for the data byte. See in Section 5.5 Device addressing (Table 8, Table 9 and Table 10) how to address the configurable device address register.

When the bus master generates a stop condition immediately after the data byte ACK bit (in the "10th bit" time slot), the internal write cycle t_W is triggered. A stop condition at any other time slot does not trigger the internal write cycle.

During the internal write cycle, serial data (SDA) is disabled internally, and the device does not respond to any requests (no ACK).

If the three bits C2, C1 and C0 have been re-configured with a correct write command, the device acknowledges if the chip enable address of the device select code is equal to the new values of C2, C1 and C0, otherwise no ACK.

Sending more than one byte aborts the write cycle (configurable device address content does not change).

Bits (C2, C1, C0 + DAL) can be updated (DAL = '0' to '1') in the same program instruction.

Figure 7. Write CDA register (data write enabled)

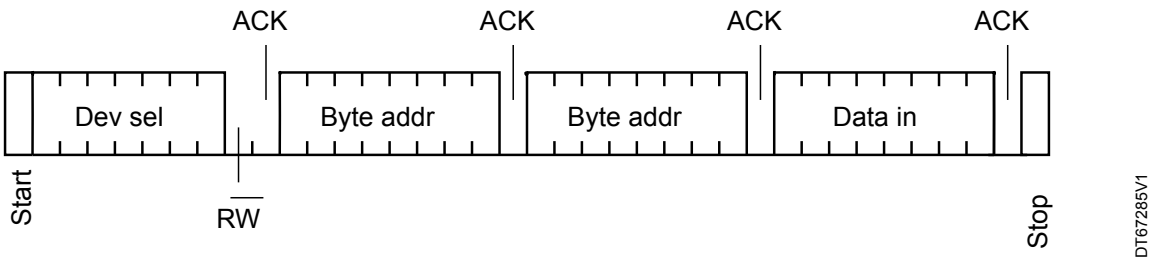
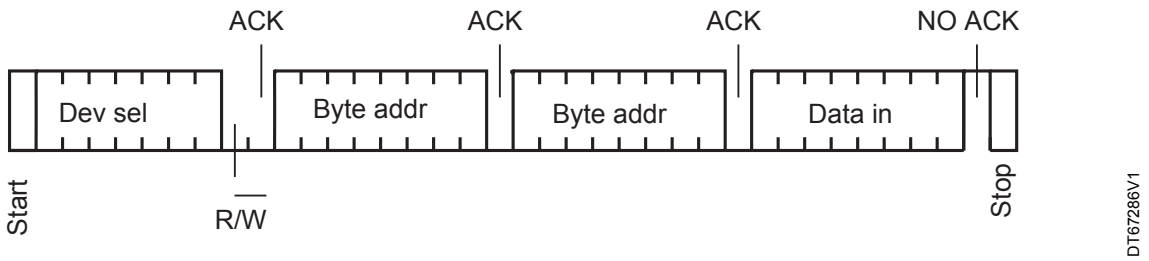


Figure 8. Write CDA register (data write inhibited by software or hardware)



6.2.3 Write operation on SWP register

Write operations on SWP register are performed according to the state of the write protect lock bit (WPL) or the status of $\overline{WC}$ line.

If the software write protection register is software protected (WPL=1) or hard protected with $\overline{WC}$ line driven high, the write operation on this register is not executed and the accompanying data bytes are not acknowledged as shown in Figure 10.

Following a start condition the bus master sends a device select code with the R/W bit ($\overline{RW}$) set to 0. The device acknowledges this, as shown in Figure 9, and waits for the address bytes where the SWP register is located. The device responds to each address byte with an acknowledge bit, and then waits for the data byte. See in Section 5.5 Device addressing (Table 8, Table 9 and Table 10) how to address the software write protection register.

When the bus master generates a stop condition immediately after the data byte ACK bit (in the "10^{th} bit" time slot), the internal write cycle t_W is triggered. A stop condition at any other time slot does not trigger the internal write cycle.

During the internal write cycle, serial data (SDA) is disabled internally, and the device does not respond to any requests (no ACK).

Sending more than one byte aborts the write cycle (software write protection register does not change).

If the SWP register is already locked or hard write protected with $\overline{WC}$ line driven high, the write operation is not executed and the accompanying data byte is not acknowledged as shown in Figure 10.

Figure 9. Write SWP register

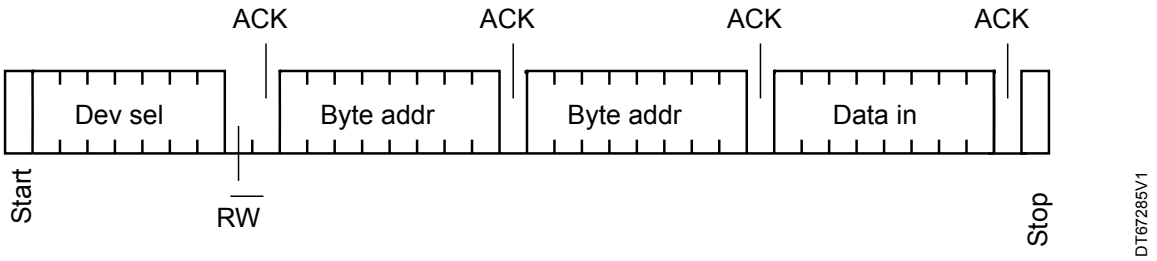
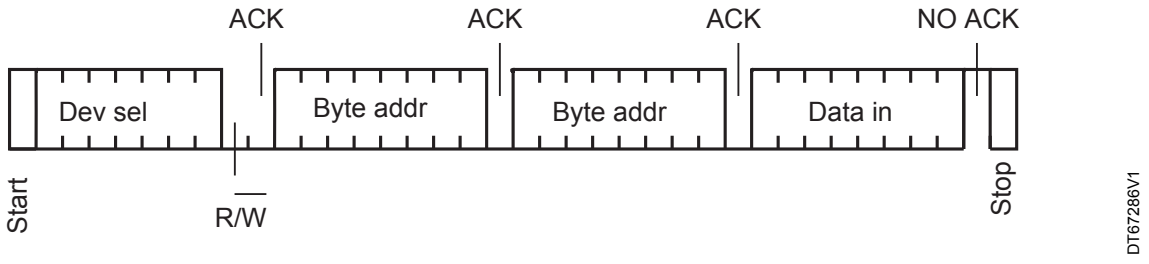


Figure 10. Write SWP register (data write inhibited by software or hardware)



6.2.4 Write operation on identification page

Following a start condition the bus master sends a device select code with the R/W bit ($R\overline{W}$) set to 0. The device acknowledges this, as shown in Figure 11, and waits for the address bytes where the identification page is located. The device responds to each address byte with an acknowledge bit, and then waits for the data byte. See in Section 5.5 Device addressing (Table 8, Table 9 and Table 10) how to address the identification page.

When the bus master generates a stop condition immediately after the data byte ACK bit (in the “10th bit” time slot), the internal write cycle t_W is triggered. The device internal address counter is automatically incremented to point to the next byte after the last modified byte. A stop condition at any other time slot does not trigger the internal write cycle.

During the internal write cycle, serial data (SDA) is disabled internally, and the device does not respond to any requests (no ACK).

If the identification page is already locked or hard write protected with $\overline{WC}$ line driven high, the write operation is not executed and the accompanying data bytes are not acknowledged as shown in Figure 12.

Figure 11. Write identification page (page unlocked)

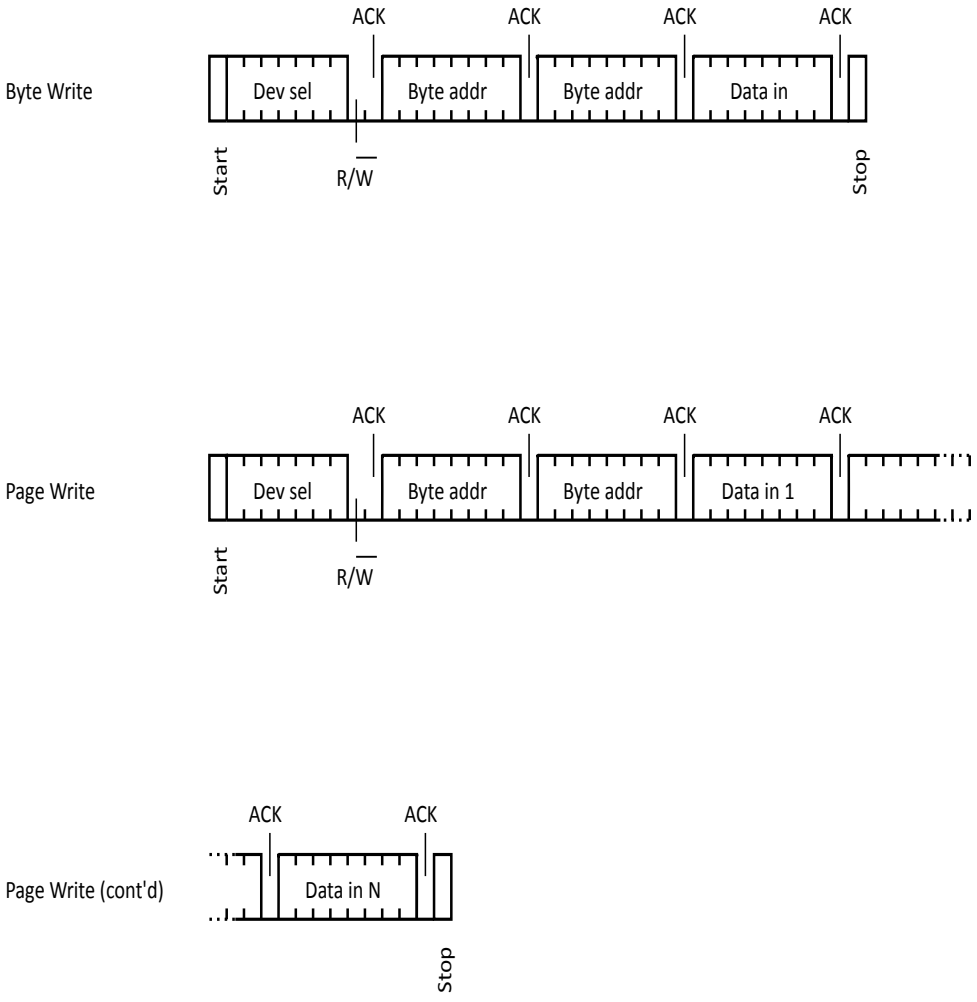
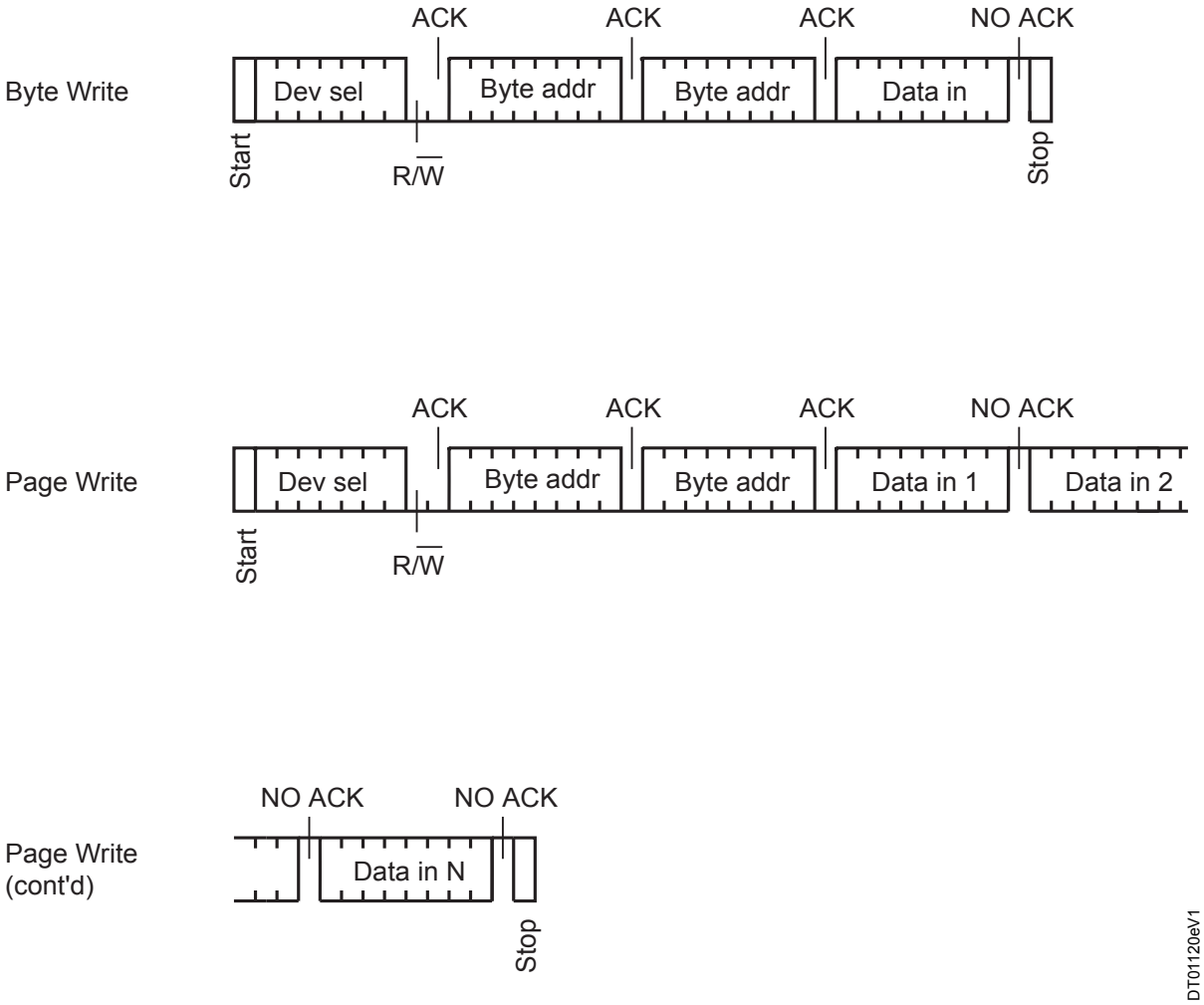


Figure 12. Write identification page (page locked or hard protected)



6.2.5 Lock operation on identification page

The lock identification page instruction (lock ID) permanently locks the identification page in read-only mode.

Following a start condition the bus master sends a device select code with the R/W bit ($\overline{RW}$) set to 0. The device acknowledges this, as shown in Figure 13, and waits for the address bytes where the identification page is located. The device responds to each address byte with an acknowledge bit, and then waits for a specific data byte value. See in Section 5.5 Device addressing (Table 8, Table 9 and Table 10) how to address the identification page.

The data byte must be equal to the binary value xxxx xx1x, where x is don't care.

When the bus master generates a stop condition immediately after the data byte ACK bit (in the "10th bit" time slot), the internal write cycle t_W is triggered. A stop condition at any other time slot does not trigger the internal write cycle.

During the internal write cycle, serial data (SDA) is disabled internally, and the device does not respond to any requests (no ACK).

If the identification page is already locked or hard write protected with $\overline{WC}$ line driven high, the write operation is not executed and the accompanying data bytes are not acknowledged as shown in Figure 14.

Figure 13. Lock operation on identification page (unlocked or data write enabled)

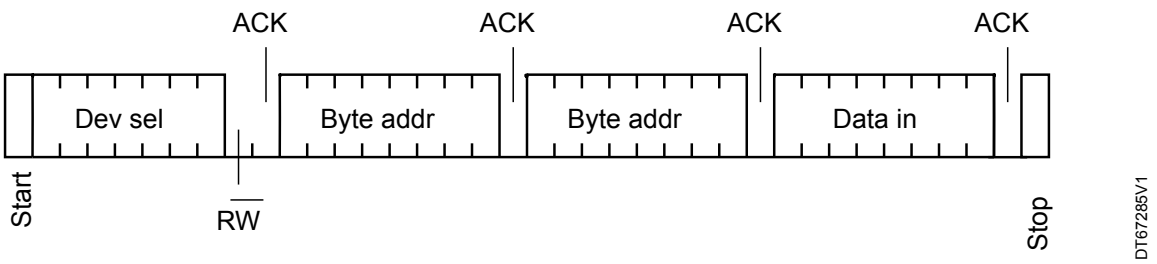
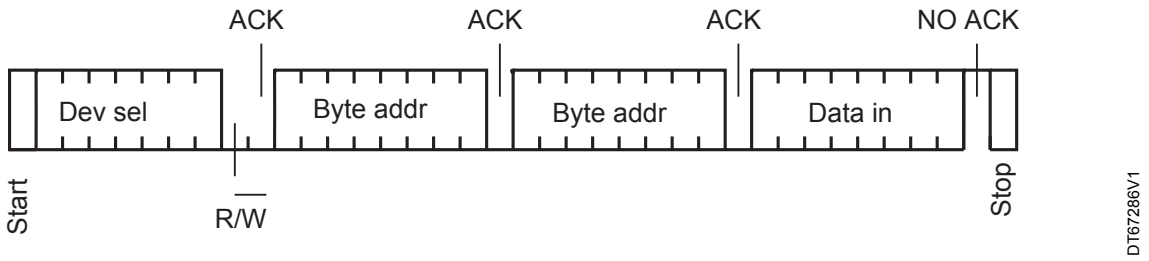


Figure 14. Lock operation on identification page (already locked or data write inhibited by hardware)



6.3 Minimizing write delays by polling on ACK

During the internal write cycle, the device disconnects itself from the bus, and writes a copy of the data from its internal latches to the memory cells. The maximum write time (tw) is shown in AC characteristics tables in Section 9 DC and AC parameters, but the typical time is shorter. To make use of this, a polling sequence can be used by the bus master.

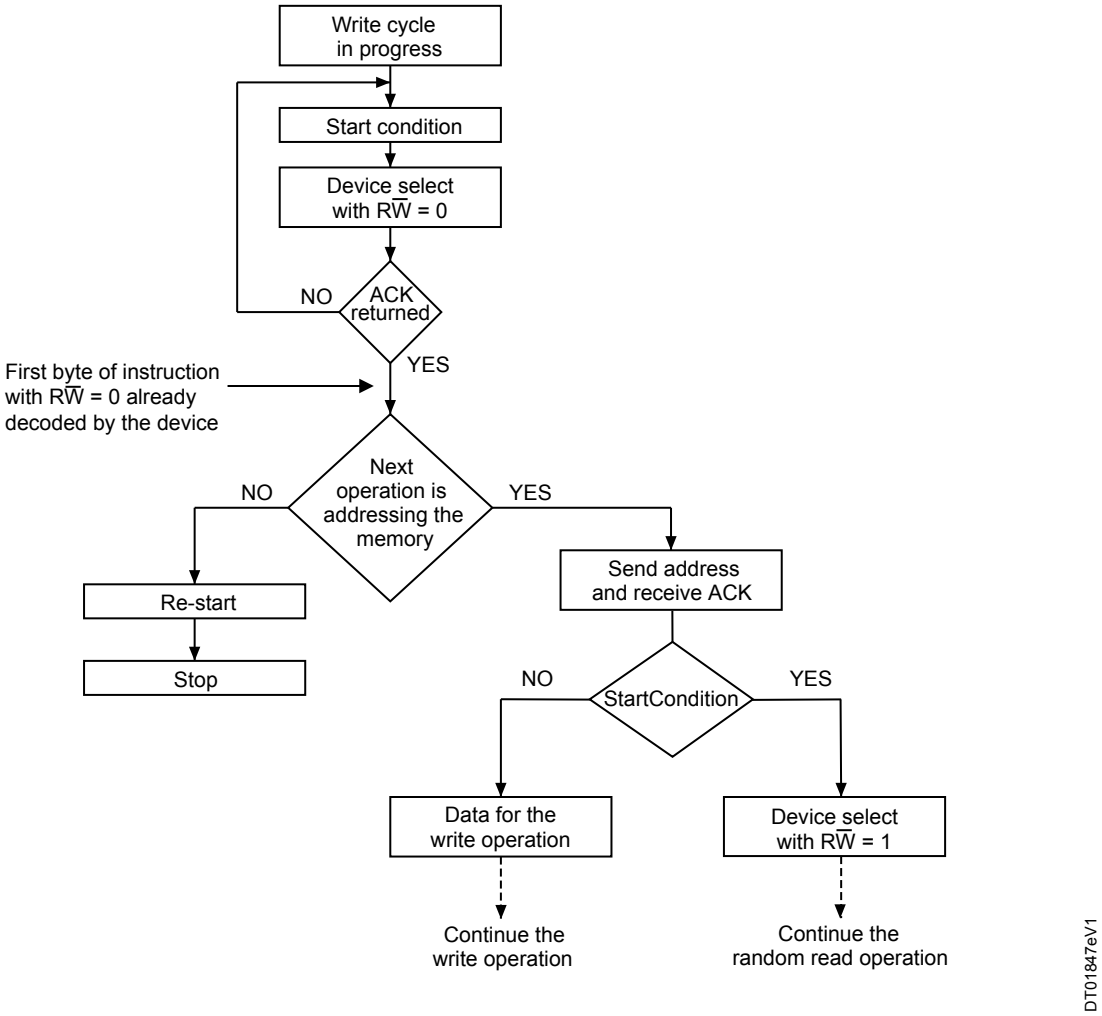
The sequence, as shown in Figure 15, is:

- Initial condition: a write cycle is in progress.
- Step 1: the bus master issues a Start condition followed by a device select code (the first byte of the new instruction).
- Step 2: if the device is busy with the internal write cycle, no Ack is returned and the bus master goes back to step 1. If the device has terminated the internal write cycle, it responds with an Ack, indicating that the device is ready to receive the second part of the instruction (the first byte of this instruction having been sent during Step 1).

Note: In case of write command to the configurable device address register when C2, C1 and C0 are re-configured, the device returns ACK only if:

- *Chip enable address of the device select code is equal to the new C2, C1 and C0 values*
- *An internal write cycle is completed (new C2, C1 and C0 values have been programmed in the chip enable register).*

Figure 15. Write cycle polling flowchart using ACK



1. The seven most significant bits of the device select code of a random read (bottom right box in the figure) must be identical to the seven most significant bits of the device select code of the write (polling instruction in the figure).

6.4 ECC (error correction code) and write cycling

The error correction code (ECC) is an internal logic function which is transparent for the I^2C communication protocol.

The ECC logic is implemented on each group of four EEPROM bytes (A group of four bytes is located at addresses [4*N, 4*N+1, 4*N+2, 4*N+3], where N is an integer). Inside a group, if a single bit out of the four bytes happens to be erroneous during a read operation, the ECC detects this bit and replaces it with the correct value. The read reliability is therefore much improved.

Even if the ECC function is performed on groups of four bytes, a single byte can be written/cycled independently. In this case, the ECC function also writes/cycles the three other bytes located in the same group (A group of four bytes is located at addresses [4*N, 4*N+1, 4*N+2, 4*N+3], where N is an integer). As a consequence, the maximum cycling budget is defined at group level and the cycling can be distributed over the 4 bytes of the group: the sum of the cycles seen by byte0, byte1, byte2 and byte3 of the same group must remain below the maximum value defined Table 15.

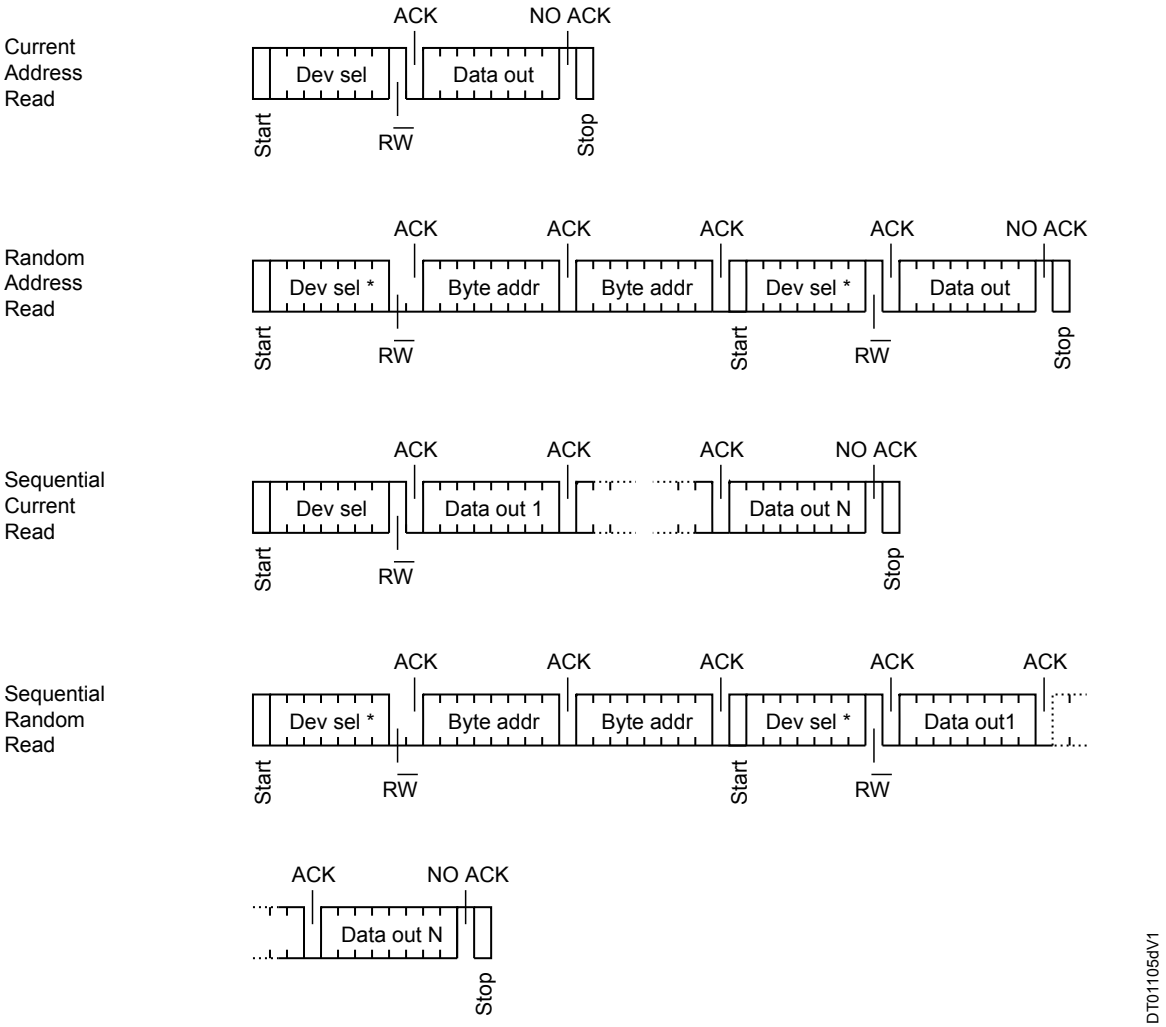
6.5 Read operations on memory array

Following a start condition the bus master sends a device select code with the R/W bit ($\overline{RW}$) set to '0'. The device acknowledges this and waits for the two bytes address. The device responds to each address byte with an acknowledge bit. Then, the bus master sends another start condition, and repeats the device select code,with the $\overline{RW}$ bit set to '1'. The device acknowledges this, and outputs the contents of the data. See in Section 5.5 Device addressing (Table 8, Table 9 and Table 10) how to address the memory array.

After each byte read (data out), the device waits for an acknowledgement (data in) during the 9th bit time. If the bus master does not acknowledge during this 9th time, the device terminates the data transfer and switches to its standby mode after a stop condition.

After the successful completion of a read operation, the device internal address counter is incremented by one, to point to the next byte address

Figure 16. Read mode sequences



*: The seven most significant bits of the device select code of a random read must be identical to the seven most significant bits of the device select code of the write.

6.5.1 Random address read

A dummy write is first performed to load the address into this address counter (as shown in Figure 16) but without sending a stop condition. Then, the bus master sends another start condition, and repeats the device select code, with the RW bit set to 1. The device acknowledges this, and outputs the contents of the addressed byte. The bus master must not acknowledge the byte, and terminates the transfer with a stop condition.

6.5.2 Current address read

For the current address read operation, following a start condition, the bus master only sends a device select code with the RW bit set to 1. The device acknowledges this, and outputs the byte addressed by the internal address counter. The counter is then incremented. The bus master terminates the transfer with a stop condition, as shown in Figure 16, without acknowledging the byte.

Note that the address counter value is defined by instructions accessing either the memory, registers or the identification page. When accessing the registers or the identification page, the address counter value is loaded with the byte location, therefore the next current address read in the memory uses this new address counter value. When accessing the memory, it is safer to always use the random address read instruction (this instruction loads the address counter with the byte location to read in the memory, see Section 6.5.1 Random address read) instead of the current address Read instruction.

6.5.3 Sequential read

This operation can be used after a current address read or a random address read. The bus master does acknowledge the data byte output, and sends additional clock pulses so that the device continues to output the next byte in sequence. To terminate the stream of bytes, the bus master must not acknowledge the last byte, and must generate a Stop condition, as shown in Figure 16.

The output data comes from consecutive addresses, with the internal address counter automatically incremented after each byte output. After the last memory address, the address counter “rolls-over”, and the device continues to output data from memory address 00h.

6.6 Read operations on features

Only the random address read or sequential random read commands are authorized to access the four additional features. The address counter contains meaningful address value only after these authorized commands have been performed.

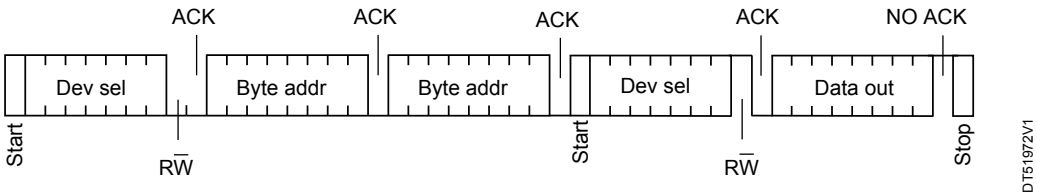
6.6.1 Read operation on DTI register

Following a start condition the bus master sends a device select code with the R/W bit ($R\overline{W}$) set to 0. The device acknowledges this and waits for the address bytes where the DTI register is located. The device responds to each address byte with an acknowledge bit. Then, the bus master sends another start condition, and repeats the device select code, with the $R\overline{W}$ bit set to 1. The device acknowledges this, and outputs the contents of the DTI register. See in Section 5.5 Device addressing (Table 8, Table 9 and Table 10) how to address the device type identifier register.

After the successful completion of a read device type identifier, the device internal address counter is not incremented by one, to point to the next byte address. Reading more than one byte loops on reading the device type identifier register value. To terminate the stream of data byte, the bus master must not acknowledge the byte, and must generate a stop condition, as shown in Figure 17.

The device type identifier register cannot be read while a write cycle (t_W) is on going.

Figure 17. Random read DTI register



*: The seven most significant bits of the device select code of a random read must be identical.

6.6.2 Read operation on CDA register

Following a start condition the bus master sends a device select code with the R/W bit ($\overline{RW}$) set to 0. The device acknowledges this and waits for the address bytes where the CDA register is located. The device responds to each address byte with an acknowledge bit. Then, the bus master sends another start condition, and repeats the device select code, with the $\overline{RW}$ bit set to 1. The device acknowledges this, and outputs the contents of the CDA register. See in Section 5.5 Device addressing (Table 8, Table 9 and Table 10) how to address the configurable device address register.

After the successful completion of a read configurable device address, the device internal address counter is not incremented by one, to point to the next byte address. Reading more than one byte loops on reading the configurable device address register value.

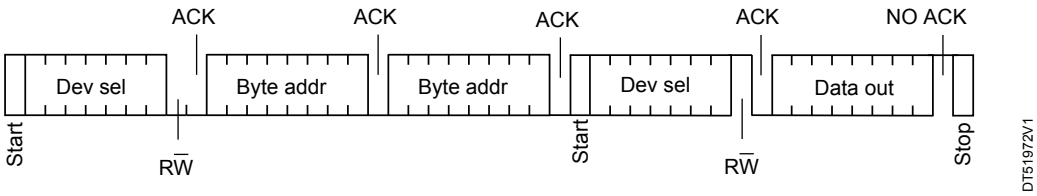
To terminate the stream of data byte, the bus master must not acknowledge the byte, and must generate a stop condition, as shown in Figure 18.

The configurable device address register cannot be read while a write cycle (t_W) is ongoing.

The configurable device address bits (C2, C1, C0) values can be checked by sending the device select code.

- If the chip enable address b3, b2, b1 sent in the device select code is matching with the C2, C1 and C0 values, device sends an ACK.
- Otherwise, device answers no ACK.

Figure 18. Random read CDA register



*: The seven most significant bits of the device select code of a random read must be identical.

6.6.3 Read operation on SWP register

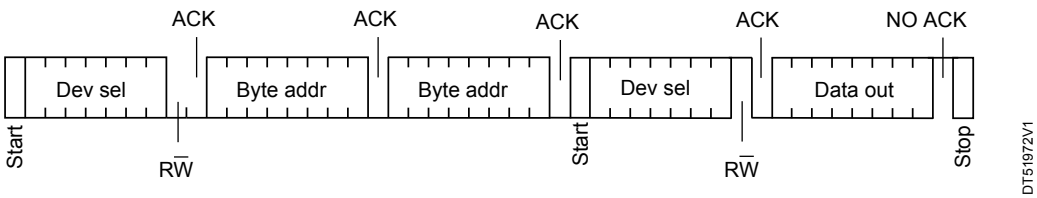
Following a start condition the bus master sends a device select code with the R/W bit ($\overline{RW}$) set to 0. The device acknowledges this and waits for the address bytes where the SWP register is located. The device responds to each address byte with an acknowledge bit. Then, the bus master sends another start condition, and repeats the device select code, with the $\overline{RW}$ bit set to 1. The device acknowledges this, and outputs the contents of the SWP register. See in Section 5.5 Device addressing (Table 8, Table 9 and Table 10) how to address the software write protection register.

After the successful completion of a read operation on SWP, the device internal address counter is not incremented by one, to point to the next byte address. Reading more than one-byte loops on reading the SWP register value.

To terminate the stream of data byte, the bus master must not acknowledge the byte, and must generate a stop condition, as shown in Figure 19.

The SWP register cannot be read while a write cycle (t_W) is ongoing.

Figure 19. Random read SWP register



*: The seven most significant bits of the device select code of a random read must be identical.

6.6.4 Read operation on identification page

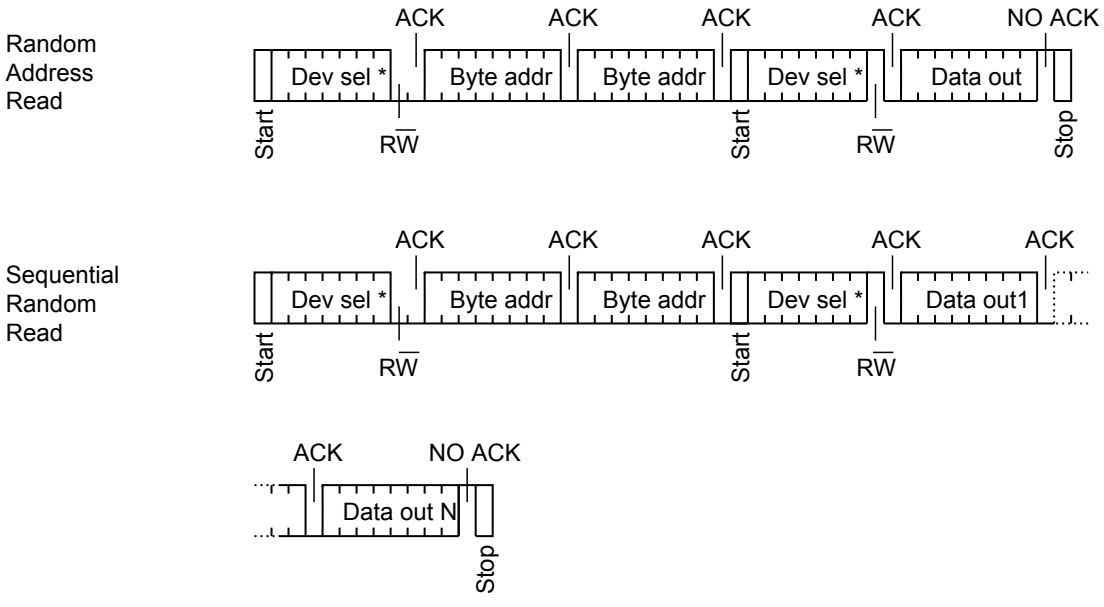
Following a start condition the bus master sends a device select code with the R/W bit ($R\overline{W}$) set to 0. The device acknowledges this and waits for the address bytes where the identification page is located. The device responds to each address byte with an acknowledge bit. Then, the bus master sends another start condition, and repeats the device select code, with the $R\overline{W}$ bit set to 1. The device acknowledges this, and outputs the contents of the identification page. See in Section 5.5 Device addressing (Table 8, Table 9 and Table 10) how to address the identification page.

After each byte read (data out), the device waits for an acknowledgement (data in) during the 9th bit time. The output data of identification page comes from consecutive addresses, with the internal address counter automatically incremented after each byte output. After the last identification page address(7Fh), the address counter “rolls-over”, and the device continues to output data from identification page address 00h.

To terminate the stream of data byte, the bus master must not acknowledge the byte, and must generate a stop condition, as shown in Figure 20.

If the bus master does not acknowledge during this 9th time, the device terminates the data transfer as shown in Figure 20 and switches to its standby mode.

Figure 20. Random read identification page



*: The seven most significant bits of the device select code of a random read must be identical.

6.6.5 Read lock status on identification page

The lock/unlock status of the identification page can be checked by transmitting a specific truncated command.

Following a start condition the bus master sends a device select code with the R/W bit ($\overline{RW}$) set to 0. The device acknowledges this and waits for the address bytes where the identification page is located. The device responds to each address byte with an acknowledge bit, and then waits for the data byte. See in Section 5.5 Device addressing (Table 8, Table 9 and Table 10) how to address the identification page.

The device returns an acknowledge bit after the data byte if the identification page is unlocked (unlock status) as shown in Figure 21, otherwise a NoAck bit as shown in Figure 22, if the identification page is locked (lock status).

Right after this, it is recommended to transmit to the device a start condition followed by a stop condition, so that:

- Start: the truncated command is not executed because the start condition resets the device internal logic
- Stop: the device is then set back into standby mode by the stop condition

Figure 21. Read lock status (identification page unlocked)

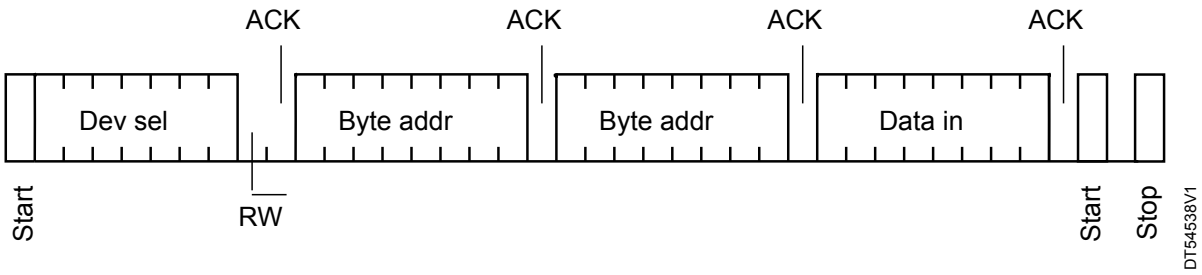
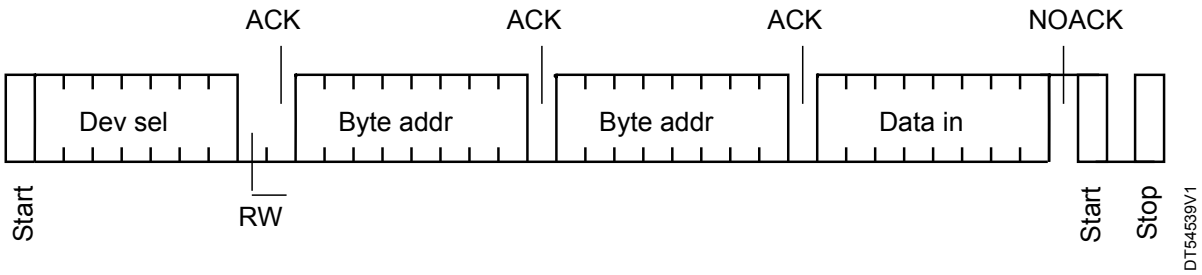


Figure 22. Read lock status (identification page locked)



7 Initial delivery state

At factory delivery, the device is delivered with:

- All the memory array bits set to 1 (each byte contains FFh)
- The DTI register locked and set to 10110001b (B1h)
- The CDA register set to 00000000b (00h)
- The SWP register set to 0000000b (00h)
- All the identification page bits set to 1 (each byte contains FFh)

8 Maximum rating

Stressing the device outside the ratings listed in Table 11 may cause permanent damage to the device. These are stress ratings only, and operation of the device at these, or any other conditions outside those indicated in the operating sections of this specification, is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

Table 11. Absolute maximum ratings

Symbol	Parameter	Min.	Max.	Unit
-	Ambient operating temperature	-40	130	°C
T_{STG}	Storage temperature	-65	150	°C
T_{LEAD}	Lead temperature during soldering	see note (1)		°C
I_{OL}	DC output current (SDA = 0)	-	5	mA
V_{IO}	Input or output range	-0.50	6.5	V
V_{CC}	Supply voltage	-0.50	6.5	V
V_{ESD}	Electrostatic pulse (Human Body model)(2)	-	4000	V

1. *Compliant with JEDEC Std J-STD-020 (for small body, Sn-Pb or Pb-free assembly), the ST ECOPACK 7191395 specification, and the European directive on Restrictions of Hazardous Substances (RoHS directive 2011/65/EU of July 2011).*
2. *Positive and negative pulses applied on different combinations of pin connections, according to ANSI/ESDA/JEDEC JS-001, C1=100 pF, R1=1500 Ω, R2=500 Ω.*

9 DC and AC parameters

This section summarizes the operating and measurement conditions, and the DC and AC characteristics of the device.

Table 12. Operating conditions

Symbol	Parameter	Min.	Max.	Unit
V_{CC}	Supply voltage	1.6	5.5	V
T_A	Ambient operating temperature	-40	85	°C
f_C	Operating clock frequency	-	1	MHz

Table 13. AC measurement conditions

Symbol	Parameter	Min.	Max.	Unit
C_{bus}	Load capacitance	-	100	pF
-	SCL input rise/fall time, SDA input fall time	-	50	ns
-	Input levels	0.2 V_{CC} to 0.8 V_{CC}		V
-	Input and output timing reference levels	0.3 V_{CC} to 0.7 V_{CC}		V

Figure 23. AC measurement I/O waveform

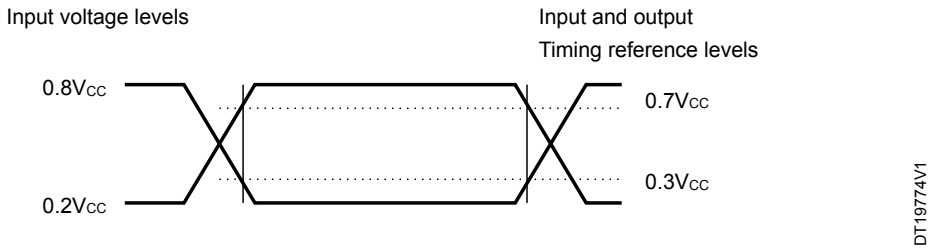


Table 14. Input parameters

Symbol	Parameter	Test condition	Min.	Max.	Unit
C_{IN}(1)	Input capacitance (SDA)	-	-	8	pF
C_{IN}(1)	Input capacitance (other pins)	-	-	6	pF
Z_L(2)	Input impedance ($\overline{WC}$)(3)	V_{IN} < 0.3 V_{CC}	30	-	kΩ
Z_H(2)		V_{IN} > 0.7 V_{CC}	500	-	kΩ

1. *Specified by design – Not tested in production*
2. *Evaluated by characterization - Not tested in production.*
3. *The memory is selected (after a start condition).*

Table 15. Cycling performance by groups of four bytes

Symbol	Parameter	Test condition	Max.	Unit
Ncycle	Write cycle endurance(1)	$T_A \leq$ 25 °C, $V_{CC}(min) < V_{CC} < V_{CC}(max)$	4,000,000	Write cycle(2)
		T_A = 85 °C, $V_{CC}(min) < V_{CC} < V_{CC}(max)$	1,200,000	

1. *The write cycle endurance is defined by characterization and qualification. For devices embedding the ECC functionality , the write cycle endurance is defined for group of four bytes located at addresses [4*N, 4*N+1, 4*N+2, 4*N+3] where N is an integer.*
2. *A Write cycle is executed when either a page write, a byte write, a write registers, a write identification page or a lock identification page instruction is decoded. When using the byte write, the page write or the write identification page, refer also to Section 6.4 ECC (error correction code) and write cycling*

Table 16. Memory cell data retention

Parameter	Test condition	Min.	Unit
Data retention(1)	T_A = 55 °C	200	Year

1. *The data retention behaviour is checked in production, while the data retention limit defined in this table is extracted from characterization and qualification results.*

Table 17. DC characteristics

Symbol	Parameter	Test conditions	Min.	Max.	Unit
I_{LI}	Input leakage current (SCL, SDA)	$V_{IN} = V_{SS}$ or V_{CC} device in standby mode	-	± 2	µA
I_{LO}	Output leakage current	SDA in Hi-Z, external voltage applied on SDA: V_{SS} or V_{CC}	-	± 2	µA
I_{CC}	Supply current (Read)	f_C = 400 kHz	-	0.5	mA
		f_C = 1 MHz	-	1	mA
I_{CC0}	Supply current (Write)	Averaged on T_W, $V_{CC} \leq$ 3.3 V	-	1(1)	mA
		Averaged on T_W, V_{CC} > 3.3 V	-	1.5(1)	
I_{CC1}	Standby supply current	Device not selected (2), $V_{IN} = V_{SS}$ or V_{CC}, V_{CC} < 2.5 V	-	1	µA
		Device not selected (2), $V_{IN} = V_{SS}$ or V_{CC}, $V_{CC} \geq$ 2.5 V	-	2	
V_{IL}	Input low voltage (SCL, SDA, $\overline{WC}$)	1.6 V ≤ V_{CC} < 2.5 V	-0.45	0.25 V_{CC}	V
		2.5 V ≤ $V_{CC} \leq$ 5.5 V	-0.45	0.30 V_{CC}	
V_{IH}	Input high voltage (SCL, SDA)	1.6 V ≤ V_{CC} < 2.5 V	0.75 V_{CC}	6.5	V
		2.5 V ≤ $V_{CC} \leq$ 5.5 V	0.70 V_{CC}	6.5	
	Input high voltage ($\overline{WC}$)	1.6 V ≤ V_{CC} < 2.5 V	0.75 V_{CC}	V_{CC}+0.6	
		2.5 V ≤ $V_{CC} \leq$ 5.5 V	0.70 V_{CC}	V_{CC}+0.6	
V_{OL}	Output low voltage	I_{OL} = 1 mA, V_{CC} =1.6 V	-	0.2	V
		I_{OL} = 2.1 mA, V_{CC} = 2.5 V or I_{OL} = 3 mA, V_{CC} = 5.5 V	-	0.4	

1. *Evaluated by characterization – not tested in production.*
2. *The device is not selected after power-up, after a read instruction (after the stop condition), or after the completion of the internal write cycle t_W (t_W is triggered by the correct decoding of a Write instruction).*

Table 18. AC characteristics in Fast-mode

Symbol	Alt.	Parameter	Min.	Max.	Unit
f_C	f_{SCL}	Clock frequency	-	400	kHz
t_{CHCL}	t_{HIGH}	Clock pulse width high	600	-	ns
t_{CLCH}	t_{LOW}	Clock pulse width low	1300	-	ns
t_{QL1QL2}(1)	t_F	SDA (out) fall time	20(2)	300	ns
t_{XH1XH2}(1)	t_R	Input signal rise time	(3)	(3)	ns
t_{XL1XL2}(1)	t_F	Input signal fall time	(3)	(3)	ns
t_{DXCH}	$t_{SU:DAT}$	Data in set up time	100	-	ns
t_{CLDX}	$t_{HD:DAT}$	Data in hold time	0	-	ns
t_{CLQX}(4)	t_{DH}	Data out hold time	100	-	ns
t_{CLQV}(5)	t_{AA}	Clock low to next data valid (access time)	-	900	ns
t_{CHDL}	$t_{SU:STA}$	Start condition setup time	600	-	ns
t_{DLCL}	$t_{HD:STA}$	Start condition hold time	600	-	ns
t_{CHDH}	$t_{SU:STO}$	Stop condition set up time	600	-	ns
t_{DHDL}	t_{BUF}	Time between Stop condition and next Start condition	1300	-	ns
t_{WLDL}(1)(6)	$t_{SU:WC}$	$\overline{WC}$ set up time (before the Start condition)	0	-	µs
t_{DHWH}(1)(7)	$t_{HD:WC}$	$\overline{WC}$ hold time (after the stop condition)	1	-	µs
t_W	t_{WR}	Write cycle time	-	4	ms
t_{NS}(1)	-	Pulse width ignored (input filter on SCL and SDA) - single glitch	-	50	ns
t_{WU}(8)(9)	-	Wake up time	-	5	µs

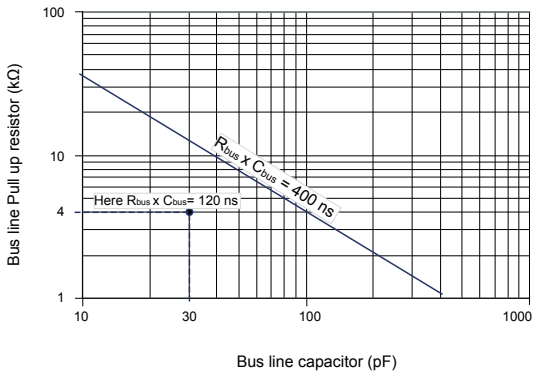
1. *Evaluated by characterization – not tested in production.*
2. *With C_L = 10 pF.*
3. *There is no min. or max. values for the input signal rise and fall times. It is however recommended by the I²C specification that the input signal rise and fall times be more than 20 ns and less than 300 ns when f_C < 400 kHz.*
4. *To avoid spurious start and stop conditions, a minimum delay is placed between SCL=1 and the falling or rising edge of SDA.*
5. *t_{CLQV} is the time (from the falling edge of SCL) required by the SDA bus line to reach either 0.3V_{CC} or 0.7V_{CC}, assuming that R_{bus} × C_{bus} time constant is within the values specified in Figure 24.*
6. *$\overline{WC}$=0 set up time condition to enable the execution of a write command.*
7. *$\overline{WC}$=0 hold time condition to enable the execution of a write command.*
8. *Wake up time: delay between the V_{CCmin} stable and the first accepted commands.*
9. *Specified by design – Not tested in production.*

Table 19. AC characteristics in Fast-mode Plus

Symbol	Alt.	Parameter	Min.	Max.	Unit
f_C	f_{SCL}	Clock frequency	-	1	MHz
t_{CHCL}	t_{HIGH}	Clock pulse width high	260	-	ns
t_{CLCH}	t_{LOW}	Clock pulse width low	500	-	ns
t_{XH1XH2}	t_R	Input signal rise time	(1)	(1)	ns
t_{XL1XL2}	t_F	Input signal fall time	(1)	(1)	ns
t_{QL1QL2}(2)	t_F	SDA (out) fall time	20(3)	120	ns
t_{DXCH}	$t_{SU:DAT}$	Data in setup time	50	-	ns
t_{CLDX}	$t_{HD:DAT}$	Data in hold time	0	-	ns
t_{CLQX}(4)	t_{DH}	Data out hold time	100	-	ns
t_{CLQV}(5)	t_{AA}	Clock low to next data valid (access time)	-	450	ns
t_{CHDL}	$t_{SU:STA}$	Start condition setup time	250	-	ns
t_{DLCL}	$t_{HD:STA}$	Start condition hold time	250	-	ns
t_{CHDH}	$t_{SU:STO}$	Stop condition setup time	250	-	ns
t_{DHDL}	t_{BUF}	Time between Stop condition and next Start condition	500	-	ns
t_{WLDL}(2)(6)	$t_{SU:WC}$	$\overline{WC}$ set up time (before the Start condition)	0	-	µs
t_{DHWH}(2)(7)	$t_{HD:WC}$	$\overline{WC}$ hold time (after the Stop condition)	1	-	µs
t_W	t_{WR}	Write cycle time	-	4	ms
t_{NS}(2)	-	Pulse width ignored (input filter on SCL and SDA)	-	50	ns
t_{WU}(8)(9)	-	Wake up time	-	5	µs

1. *There is no min. or max. values for the input signal rise and fall times. It is however recommended by the I²C specification that the input signal rise and fall times be less than 120 ns when f_C < 1 MHz.*
2. *Evaluated by characterization – not tested in production.*
3. *With CL = 10 pF.*
4. *To avoid spurious Start and Stop conditions, a minimum delay is placed between SCL=1 and the falling or rising edge of SDA.*
5. *t_{CLQV} is the time (from the falling edge of SCL) required by the SDA bus line to reach either 0.3 V_{CC} or 0.7 V_{CC}, assuming that the Rbus × Cbus time constant is within the values specified in Figure 25.*
6. *$\overline{WC}$=0 set up time condition to enable the execution of a WRITE command.*
7. *$\overline{WC}$=0 hold time condition to enable the execution of a WRITE command.*
8. *Wake up time: delay between the V_{CCmin} stable and the first accepted commands.*
9. *Specified by design – Not tested in production.*

Figure 24. Maximum R_{bus} value versus bus parasitic capacitance (C_{bus}) for an I^2C bus at maximum frequency f_C = 400 kHz



The R_{bus} x C_{bus} time constant must be below the 400 ns time constant line represented on the left

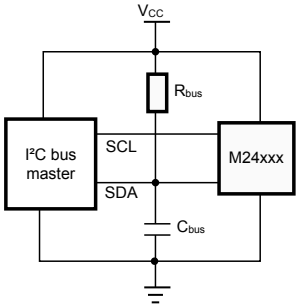
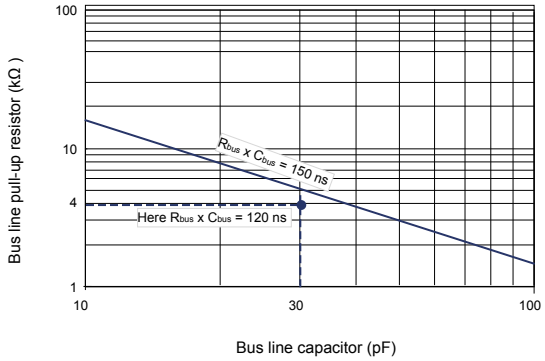


Figure 25. Maximum R_{bus} value versus bus parasitic capacitance (C_{bus}) for an I^2C bus at maximum frequency f_C = 1 MHz



The R_{bus} x C_{bus} time constant must be below the 150 ns time constant line represented on the left

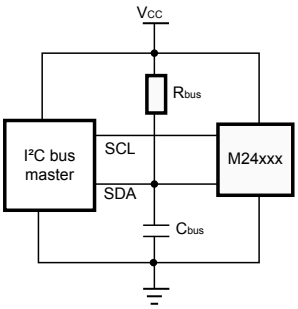
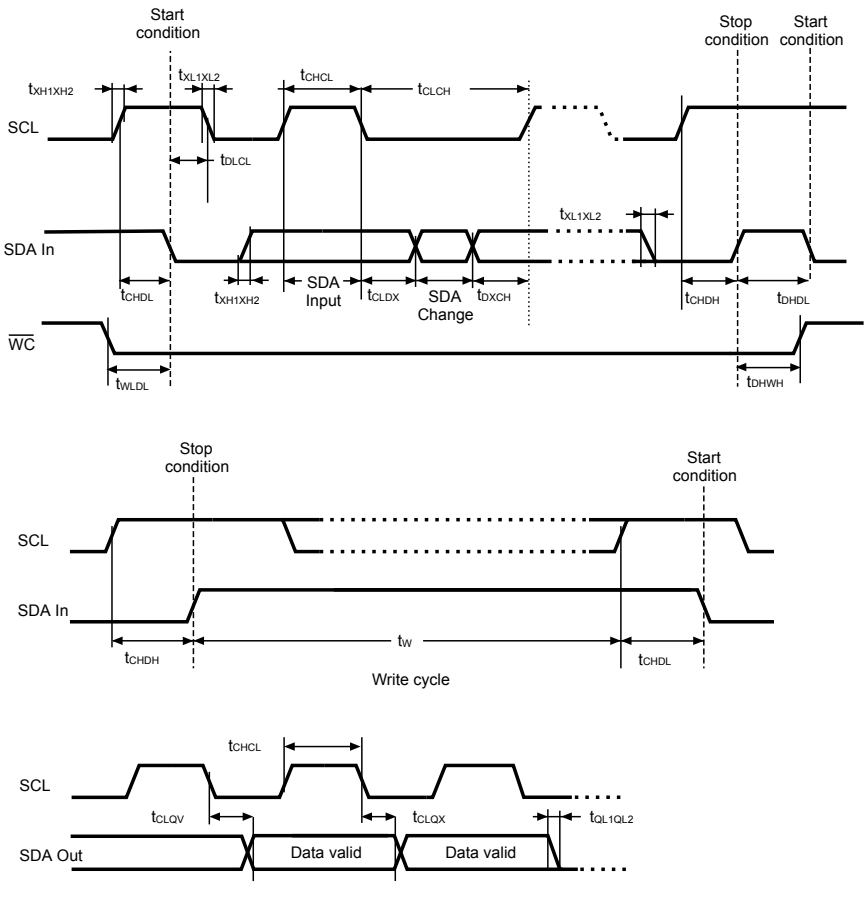


Figure 26. **AC waveforms**



DT00795IV1

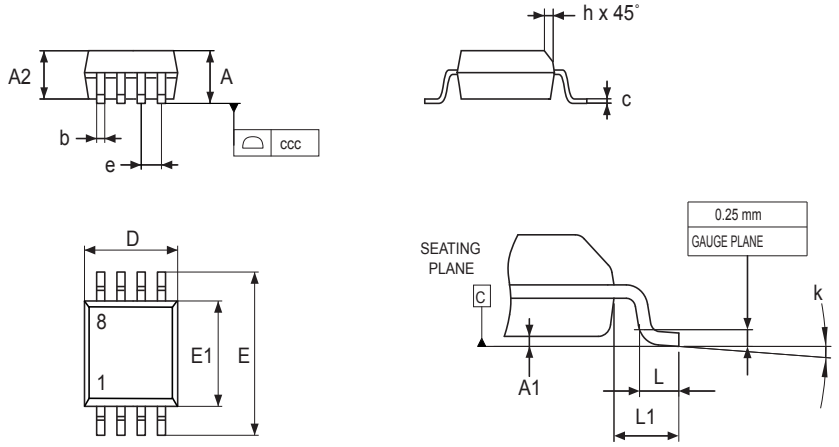
10 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK packages, depending on their level of environmental compliance. ECOPACK specifications, grade definitions and product status are available at: www.st.com. ECOPACK is an ST trademark.

10.1 SO8N package information

This SO8N is an 8-lead, 4.9 x 6 mm, plastic small outline, 150 mils body width, package.

Figure 27. SO8N – Outline



1. Drawing is not to scale.

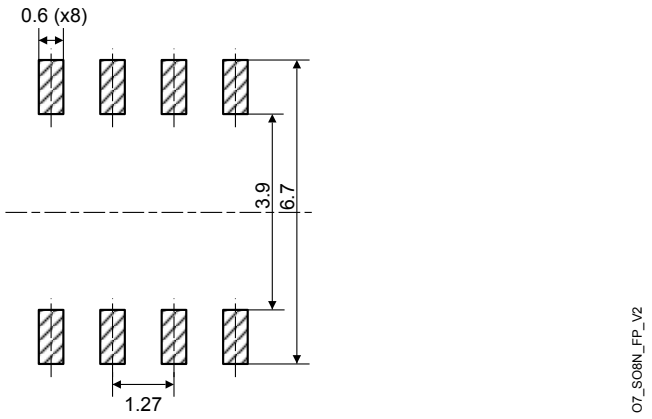
Table 20. SO8N – Mechanical data

Symbol	millimeters			inches [1]		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	-	-	1.750	-	-	0.0689
A1	0.100	-	0.250	0.0039	-	0.0098
A2	1.250	-	-	0.0492	-	-
b	0.280	-	0.480	0.0110	-	0.0189
c	0.170	-	0.230	0.0067	-	0.0091
D[2]	4.800	4.900	5.000	0.1890	0.1929	0.1969
E	5.800	6.000	6.200	0.2283	0.2362	0.2441
E1[3]	3.800	3.900	4.000	0.1496	0.1535	0.1575
e	-	1.270	-	-	0.0500	-
h	0.250	-	0.500	0.0098	-	0.0197
k	0°	-	8°	0°	-	8°
L	0.400	-	1.270	0.0157	-	0.0500
L1	-	1.040	-	-	0.0409	-
ccc	-	-	0.100	-	-	0.0039

1. *Values in inches are converted from mm and rounded to four decimal digits.*
2. *Dimension “D” does not include mold flash, protrusions or gate burrs. Mold flash, protrusions or gate burrs shall not exceed 0.15 mm per side*
3. *Dimension “E1” does not include interlead flash or protrusions. Interlead flash or protrusions shall not exceed 0.25 mm per side.*

Note: The package top may be smaller than the package bottom. Dimensions D and E1 are determinated at the outermost extremes of the plastic body exclusive of mold flash, tie bar burrs, gate burrs and interleads flash, but including any mismatch between the top and bottom of plastic body. Measurement side for mold flash, protusions or gate burrs is bottom side.

Figure 28. SO8N - Footprint example

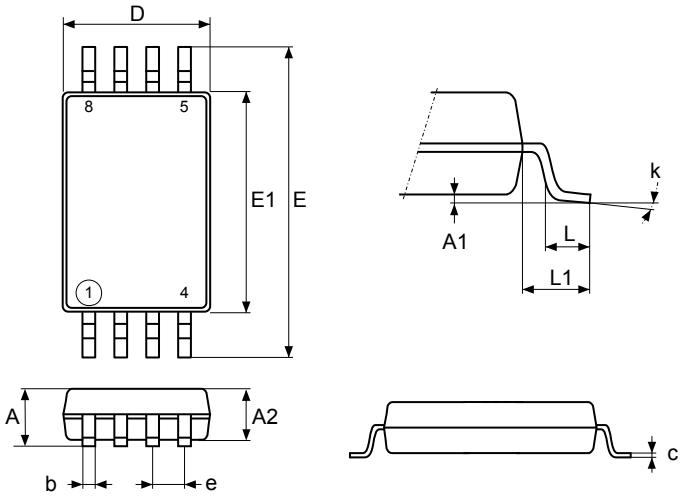


1. Dimensions are expressed in millimeters.

10.2 TSSOP8 package information

This TSSOP is an 8-lead, 3 x 6.4 mm, 0.65 mm pitch, thin shrink small outline package.

Figure 29. TSSOP8 – Outline



1. Drawing is not to scale.

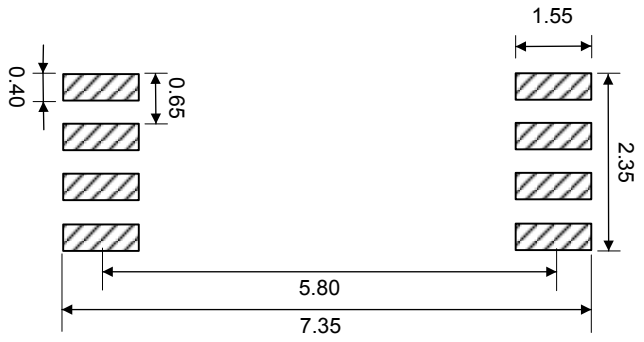
Table 21. TSSOP8 – Mechanical data

Symbol	millimeters			inches (1)		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	-	-	1.200	-	-	0.0472
A1	0.050	-	0.150	0.0020	-	0.0059
A2	0.800	1.000	1.050	0.0315	0.0394	0.0413
b	0.190	-	0.300	0.0075	-	0.0118
c	0.090	-	0.200	0.0035	-	0.0079
D(2)	2.900	3.000	3.100	0.1142	0.1181	0.1220
e	-	0.650	-	-	0.0256	-
E	6.200	6.400	6.600	0.2441	0.2520	0.2598
E1(3)	4.300	4.400	4.500	0.1693	0.1732	0.1772
L	0.450	0.600	0.750	0.0177	0.0236	0.0295
L1	-	1.000	-	-	0.0394	-
k	0°	-	8°	0°	-	8°
aaa	-	-	0.100	-	-	0.0039

1. *Values in inches are converted from mm and rounded to four decimal digits.*
2. *Dimension “D” does not include mold flash, protrusions or gate burrs. Mold flash, protrusions or gate burrs shall not exceed 0.15 mm per side*
3. *Dimension “E1” does not include interlead flash or protrusions. Interlead flash or protrusions shall not exceed 0.25 mm per side.*

Note: The package top may be smaller than the package bottom. Dimensions D and E1 are determinated at the outermost extremes of the plastic body exclusive of mold flash, tie bar burrs, gate burrs and interleads flash, but including any mismatch between the top and bottom of plastic body. Measurement side for mold flash, protusions or gate burrs is bottom side.

Figure 30. TSSOP8 – Footprint example

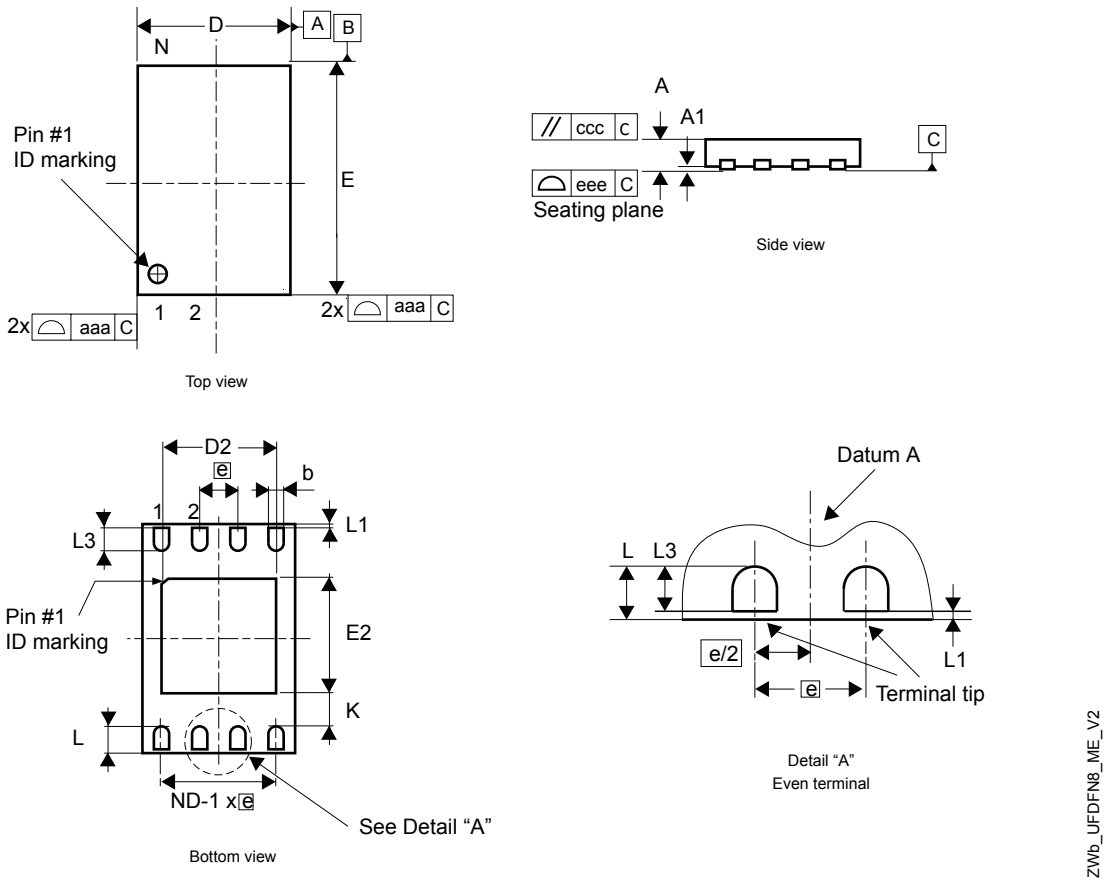


1. Dimensions are expressed in millimeters.

10.3 UFDFPN8 (DFN8) package information

This UFDFPN is a 8-lead, 2 x 3 mm, 0.5 mm pitch ultra thin profile fine pitch dual flat package.

Figure 31. UFDFPN8 - Outline



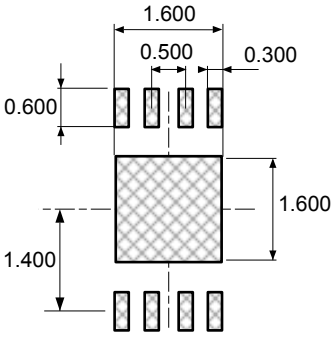
1. Maximum package warpage is 0.05 mm.
2. Exposed copper is not systematic and can appear partially or totally according to the cross section.
3. Drawing is not to scale.
4. The central pad (the area E2 by D2 in the above illustration) must be either connected to V_{SS} or left floating (not connected) in the end application.

Table 22. UFDFPN8 - Mechanical data

Symbol	millimeters			inches[1]		
	Min	Typ	Max	Min	Typ	Max
A	0.450	0.550	0.600	0.0177	0.0217	0.0236
A1	0.000	0.020	0.050	0.0000	0.0008	0.0020
b[2]	0.200	0.250	0.300	0.0079	0.0098	0.0118
D	1.900	2.000	2.100	0.0748	0.0787	0.0827
D2	1.200	-	1.600	0.0472	-	0.0630
E	2.900	3.000	3.100	0.1142	0.1181	0.1220
E2	1.200	-	1.600	0.0472	-	0.0630
e	-	0.500	-	-	0.0197	-
K	0.300	-	-	0.0118	-	-
L	0.300	-	0.500	0.0118	-	0.0197
L1	-	-	0.150	-	-	0.0059
L3	0.300	-	-	0.0118	-	-
aaa	-	-	0.150	-	-	0.0059
bbb	-	-	0.100	-	-	0.0039
ccc	-	-	0.100	-	-	0.0039
ddd	-	-	0.050	-	-	0.0020
eee[3]	-	-	0.080	-	-	0.0031

1. *Values in inches are converted from mm and rounded to four decimal digits.*
2. *Dimension b applies to plated terminal and is measured between 0.15 and 0.30 mm from the terminal tip.*
3. *Applied for exposed die paddle and terminals. Exclude embedding part of exposed die paddle from measuring.*

Figure 32. UFDFPN8 - Footprint example



ZWb_UFDFN8_FP_V2

1. Dimensions are expressed in millimeters.

11 Ordering information

Table 23. Ordering information scheme

Example:	M24	512E	- F	MN	6	T	P
Device type							
M24 = I^2C serial access EEPROM							
Device function							
512E = 512 Kbit (64 K x 8 bit)							
Operating voltage(1)							
F = V_{CC} = 1.6 V to 5.5 V							
Package(2)							
MN = SO8 (150 mil width)							
DW = TSSOP8 (169 mil width)							
MC = UFDFPN8 (DFN8)							
Device grade							
6 = Industrial device tested with standard test flow over -40 to 85 °C							
Option							
T = Tape and reel packing							
blank = tube packing							
Plating technology							
P or G = ECOPACK2							

1. *Products with finished good M24512EFMN6TPV0B or with top marking 24512FP and KxxxV on the second line are associated to the datasheet M24512E-F revision 1 - October 07,2022.*
2. *ECOPACK2 (RoHS compliant and free of brominated, chlorinated and antimony oxide flame retardants).*

Note: For a list of available options (memory, package, and so on) or for further information on any aspect of this device, contact your nearest ST sales office.

Note: Parts marked as ES or E or accompanied by an Engineering Sample notification letter are not yet qualified and therefore not approved for use in production. ST is not responsible for any consequences resulting from such use. In no event will ST be liable for the customer using any of these engineering samples in production. ST's Quality department must be contacted prior to any decision to use these engineering samples to run a qualification activity.

Revision history

Table 24. **Document revision history**

Date	Revision	Changes
07-Oct-2022	1	Initial release
13-Feb-2023	2	Added TSSOP8 and UFDFPN8 packages. Note 1 in Table 23. Ordering information scheme Updated: • minimum Voltage supply from 2.5 V to 1.6 V • Section 4.1 Device type identifier register (DTI), Section 4.2 Configurable device address register (CDA), Section 4.3 Software write protection register (SWP), Section 6.2.3 Write operation on SWP register • Table 14. Input parameters, Table 17. DC characteristics

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